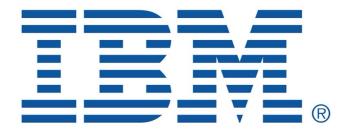
#### IBM LinuxONE



## The IBM z15 Chip is Awesome

## A LinuxONE III Story

Monte Bauman

LinuxONE Technical Support Specialist

**IBM Columbus** 

mbauman@us.ibm.com

June 2021









Let's Get Started...

# INTRODUCTION



## Abstract

The z15 chips is awesome. What follows are 9.1 Billion reasons why.

Moore's Law used to be awesome.... and sort-of still is.

- "Atoms ain't getting smaller" ... and "the speed of light ain't getting faster"
  - And hence Moore's Law is "underperforming"
- But the demand for ever bigger and faster computing systems remains
  - Consumers know what they want ... they just don't know what they are asking for
- Computer scientists and engineers must meet design challenges in new ways
  - Bigger problems requires bigger thinking
- The IBM Z chip and the platforms it powers (IBM Z and LinuxONE) have been "stepping up" to the challenge and this presentation will illustrate strides made in hardware and software to make the platform excel

The numbers, they do tell a tale. This talk will examine the evolution of CMOS microprocessor technology on the mainframe platform. We will examine the intriguing relationship between MIPS and MHz, and between transistors, chips, and cores. We will observe the past and current effects of "Moore's Law", and we will look at equations (yes, equations!) suggesting how to combat computer science physics. Microprocessor engineers have quite a challenge ahead, what will they think of next?

### Monte Bauman ... mbauman@us.ibm.com

IBM Technical Support Specialist - helping clients build risk mitigated operationally excellent economic server solutions.

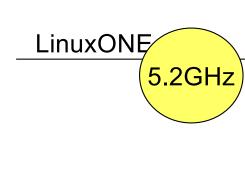
- Monte Bauman helps client's design and deploy risk mitigated operationally excellent superhyperconverged server solutions using IBM LinuxONE technologies provided by IBM and by the LinuxONE partner ecosystem.
- Monte Bauman, Certified IT Specialist and z Systems Technical Support Professional, began a career in IT in 1983 hiring into the IBM Glendale Lab where he assisted a development team to build and test mid-range mainframe servers (4300s, 9370s, 9221s). Monte was given a Division Award for work on STX/370, a diagnostic operating system. Monte Bauman became a Large Systems Systems Engineer (SE) in January of 1991 in Columbus Ohio working with enterprise clients specializing in 9021 systems support, enterprise printing support (3800/3900), and MVS support. In the mid 90's Monte Bauman became a mainframe seller for a time, before returning in late 90's to the role of a regionally designated specialist large systems SE. Monte Bauman became a "new workloads" specialist at the turn of the century, technically supporting customers as they embarked upon emerging technologies on the mainframe, such as Java and Business Intelligence and Linux. The past several years Monte Bauman has been focused on LinuxONE and Fit for Purpose analysis, helping customers understand the fit of z Systems Linux solutions as well as the processes appropriate to repeatedly and effectively map software to hardware meeting IT optimization criteria for requirements and cost.



Let's Get to the Core of this ...

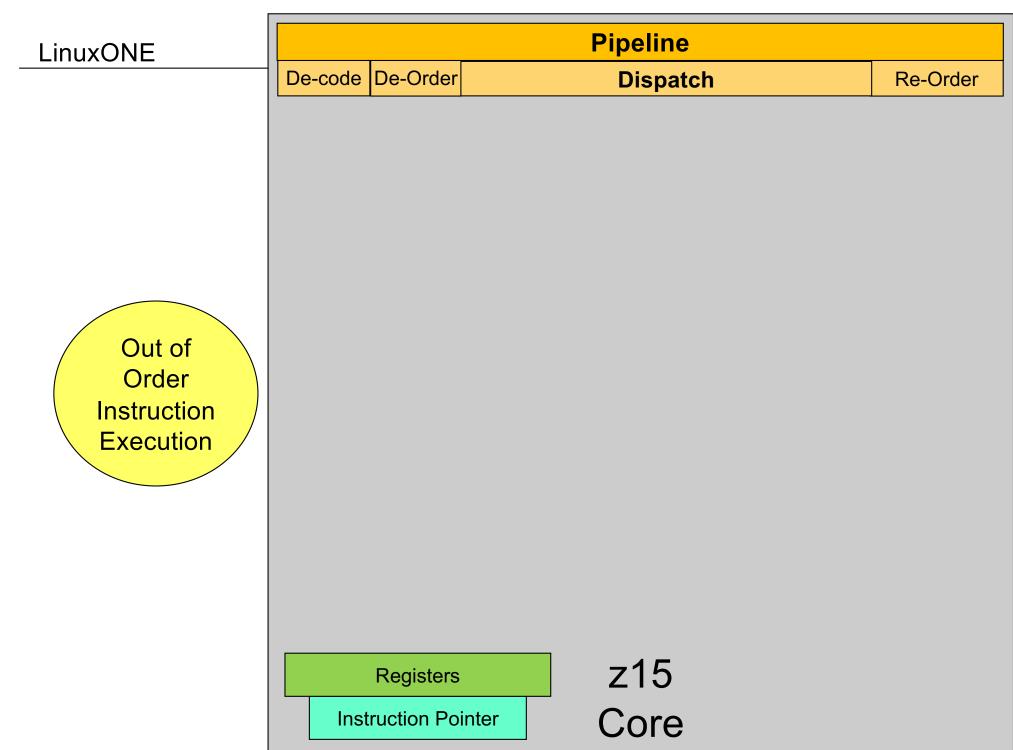
# **THE Z15 CORE**

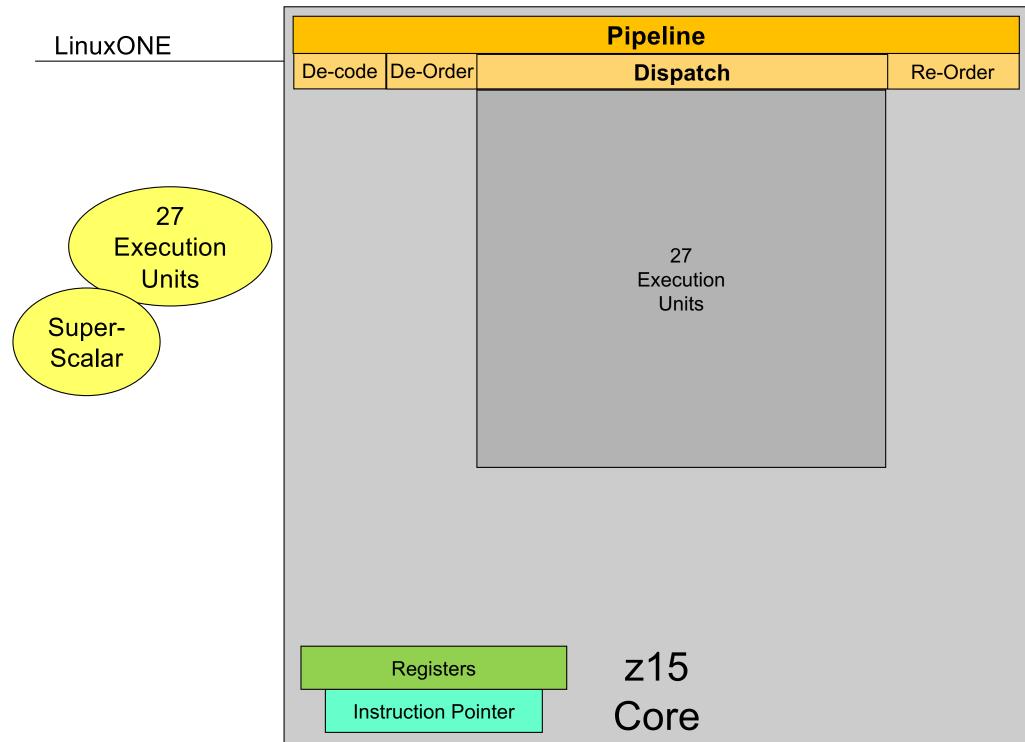
### z15 Core



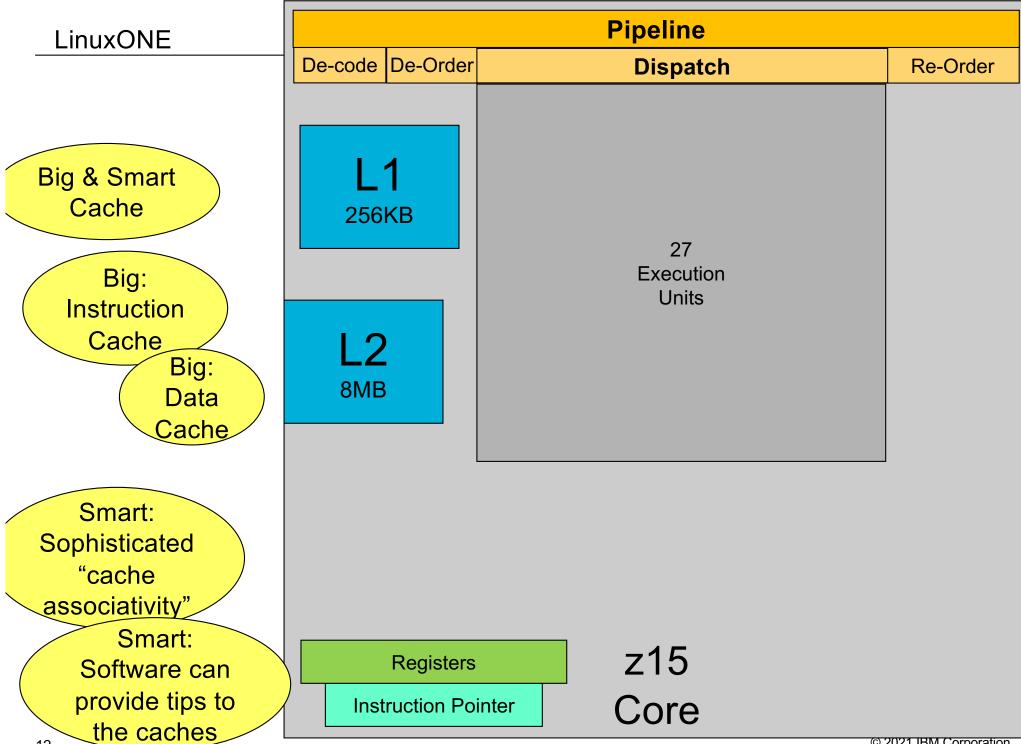
### **Pipeline**

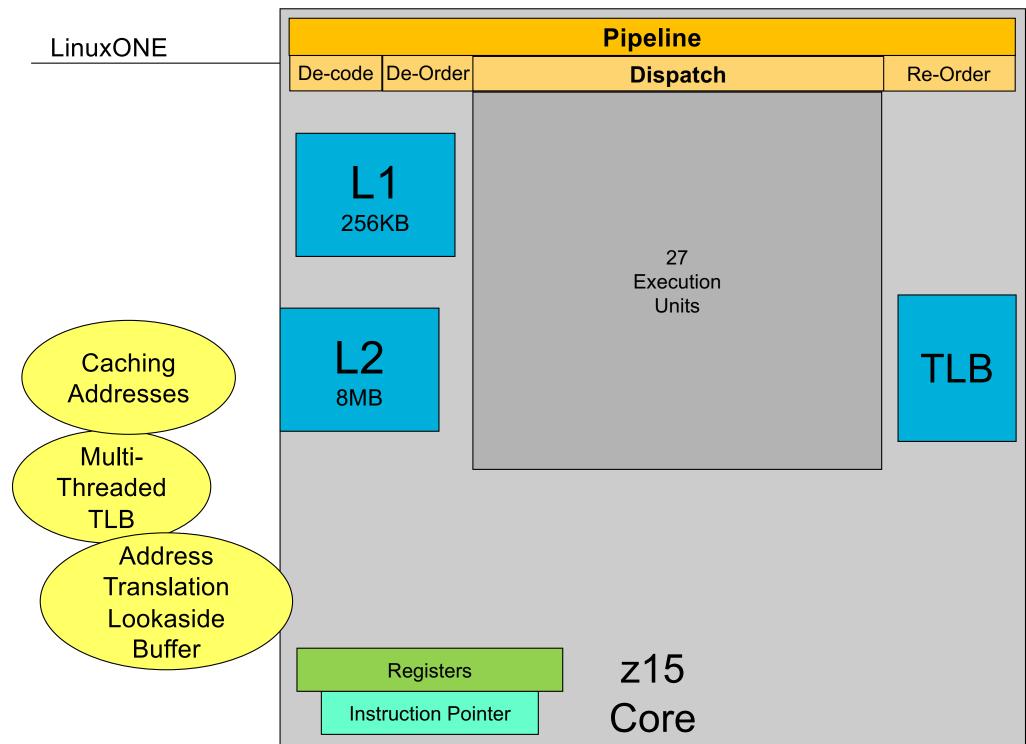
Registers	z15
Instruction Pointer	Core

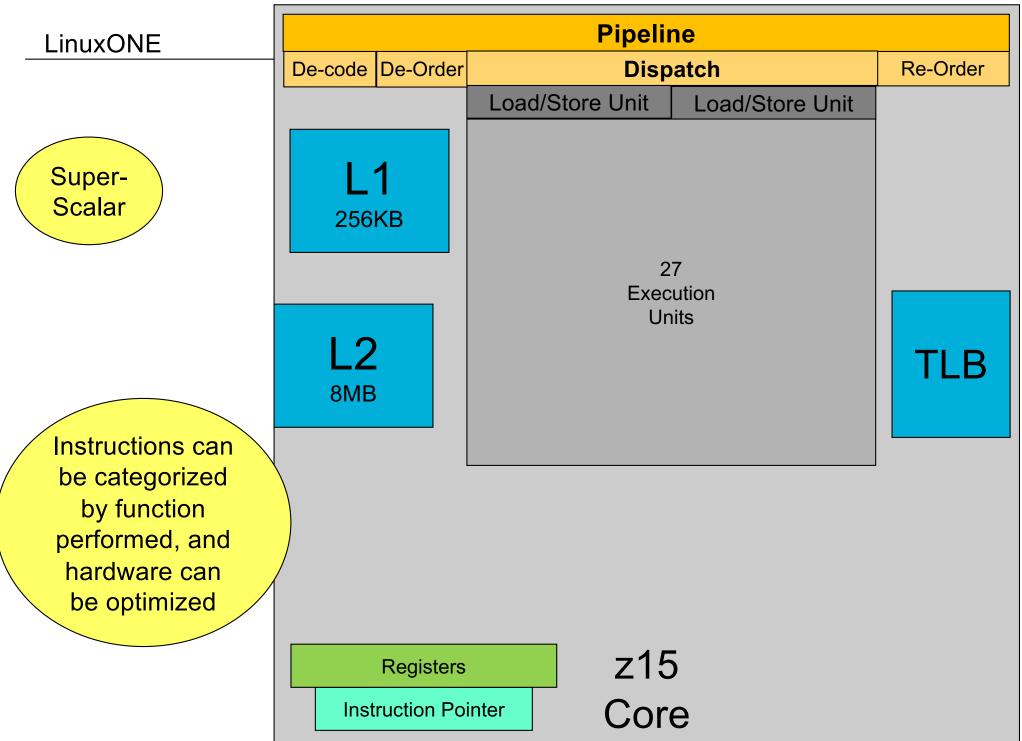


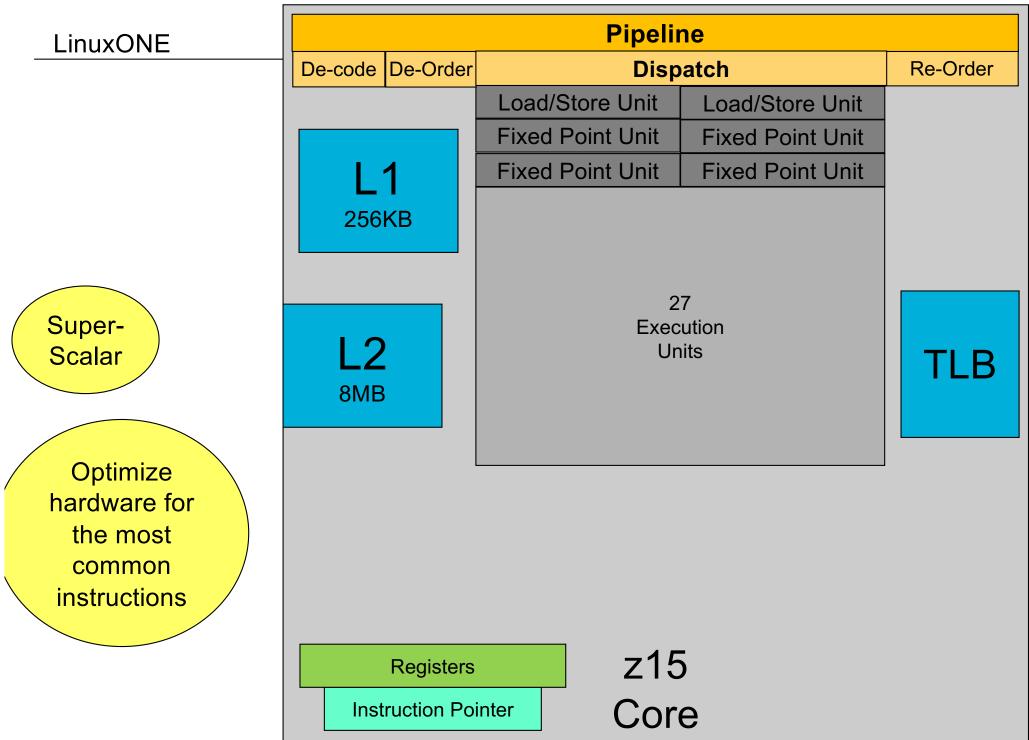


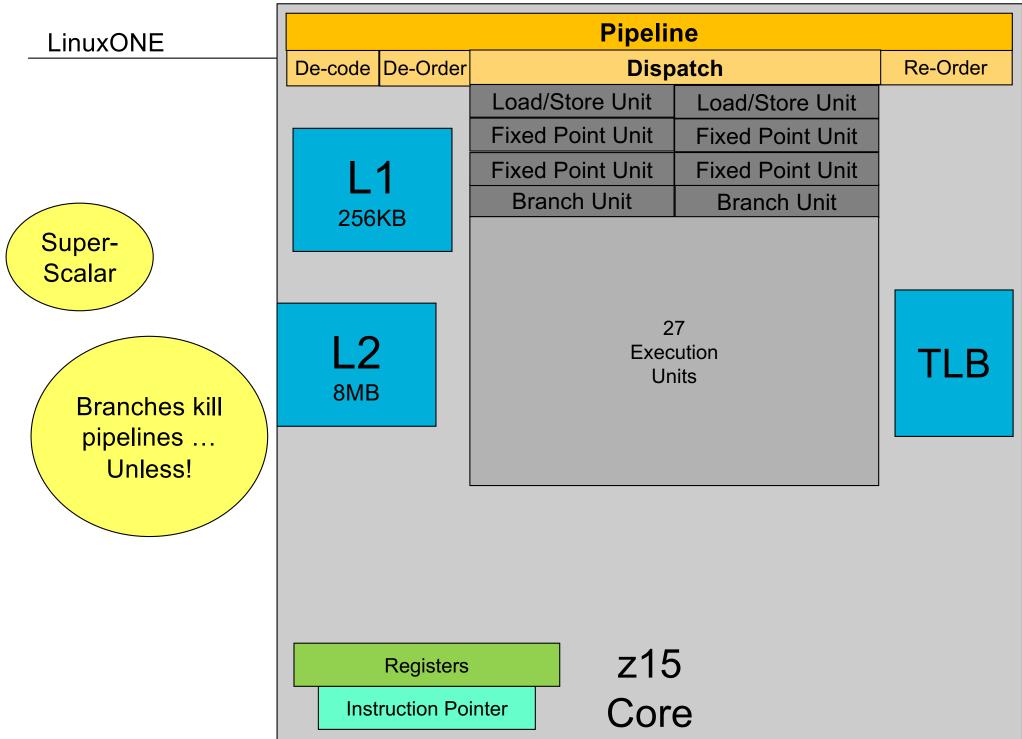
LinuxONE	Pipeline					
	De-code De-Order		Dispatch		Re-Order	
	L1 256KB		27 Execution Units			
Big & Smart Cache	Registers		z15			
	Instruction Po	inter	z15 Core			

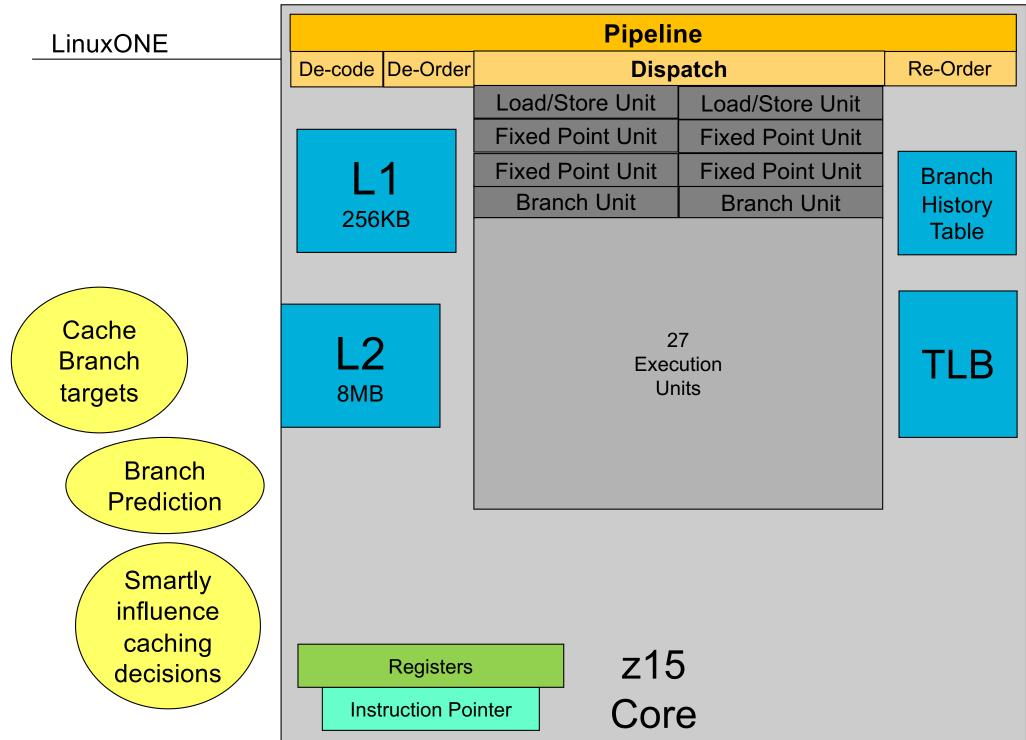


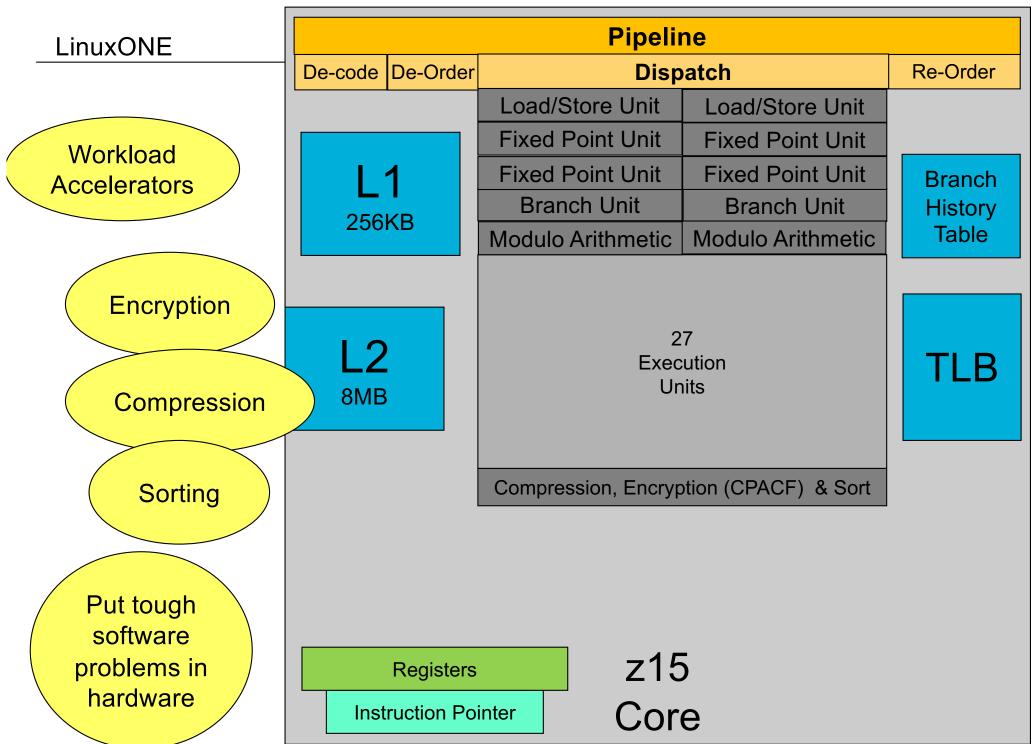


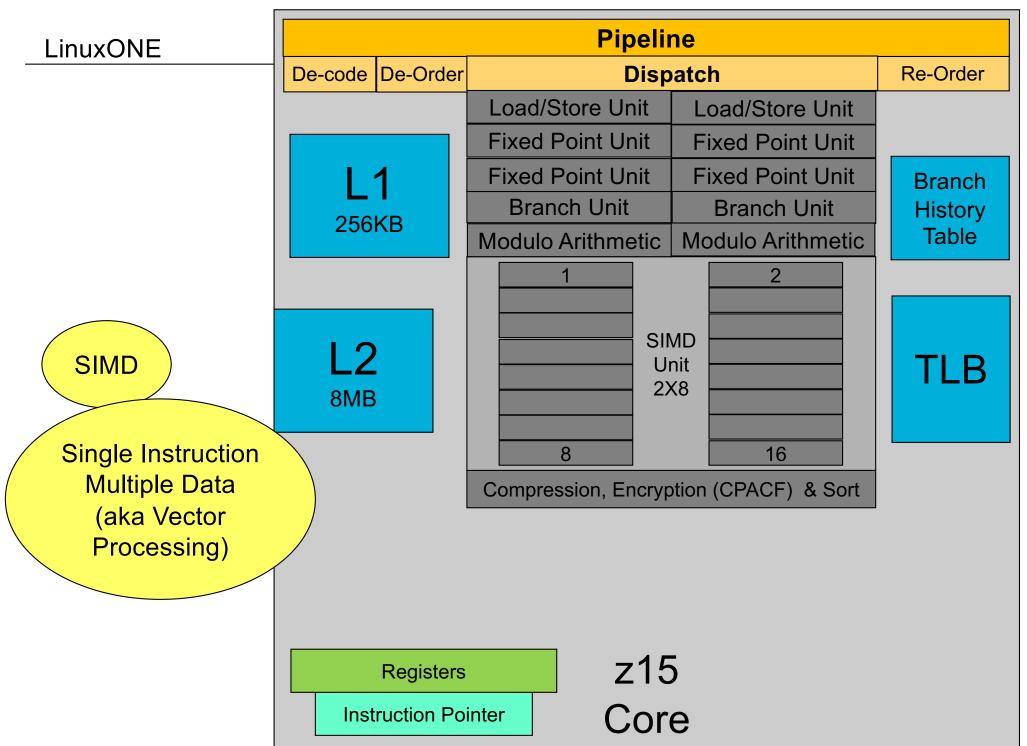


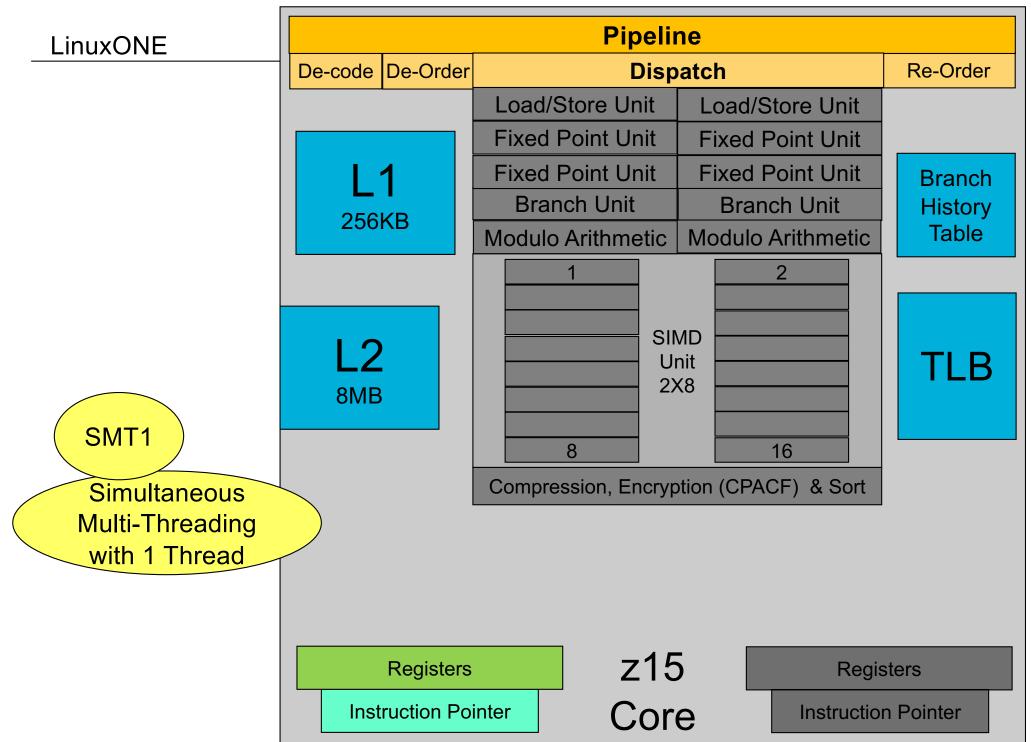


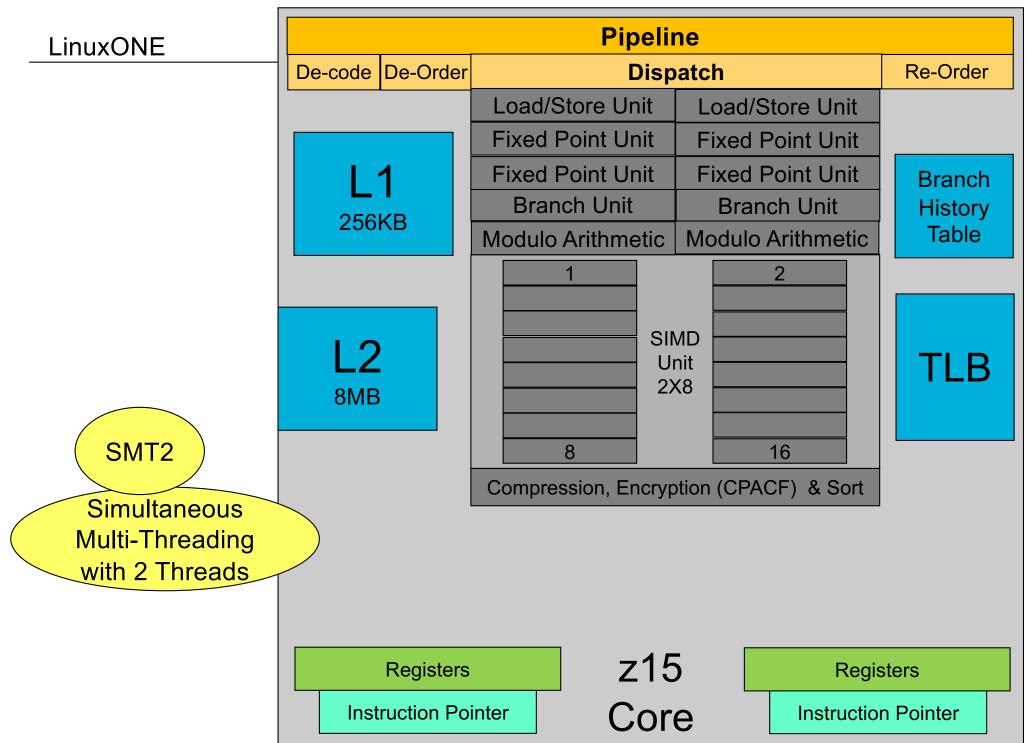


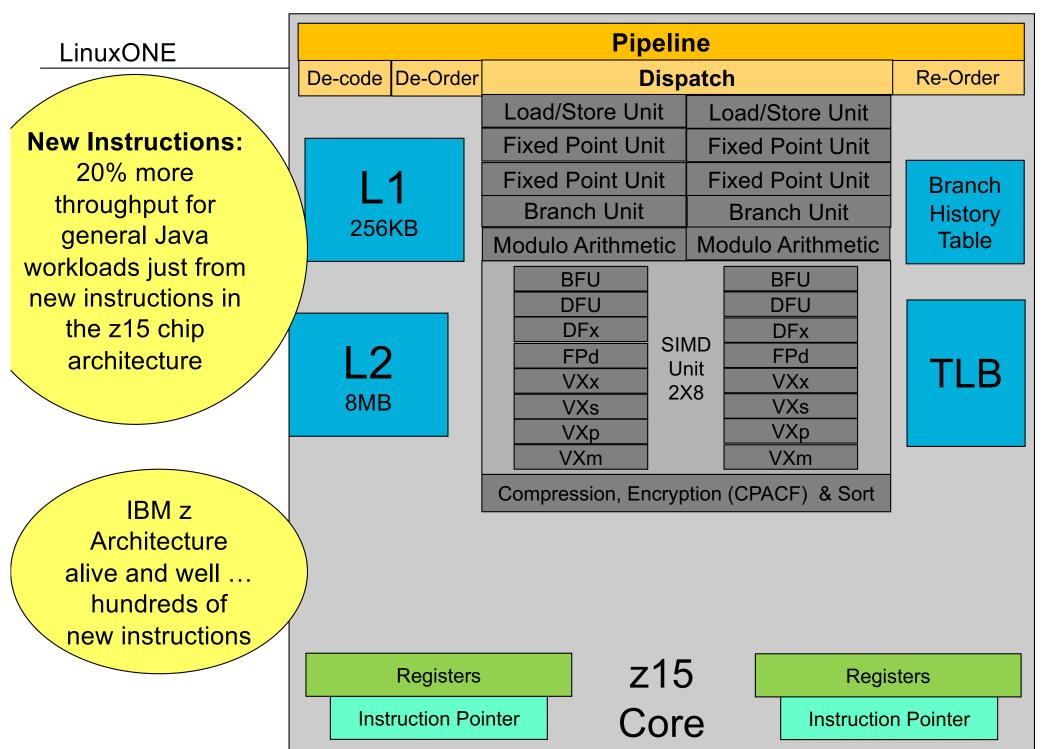


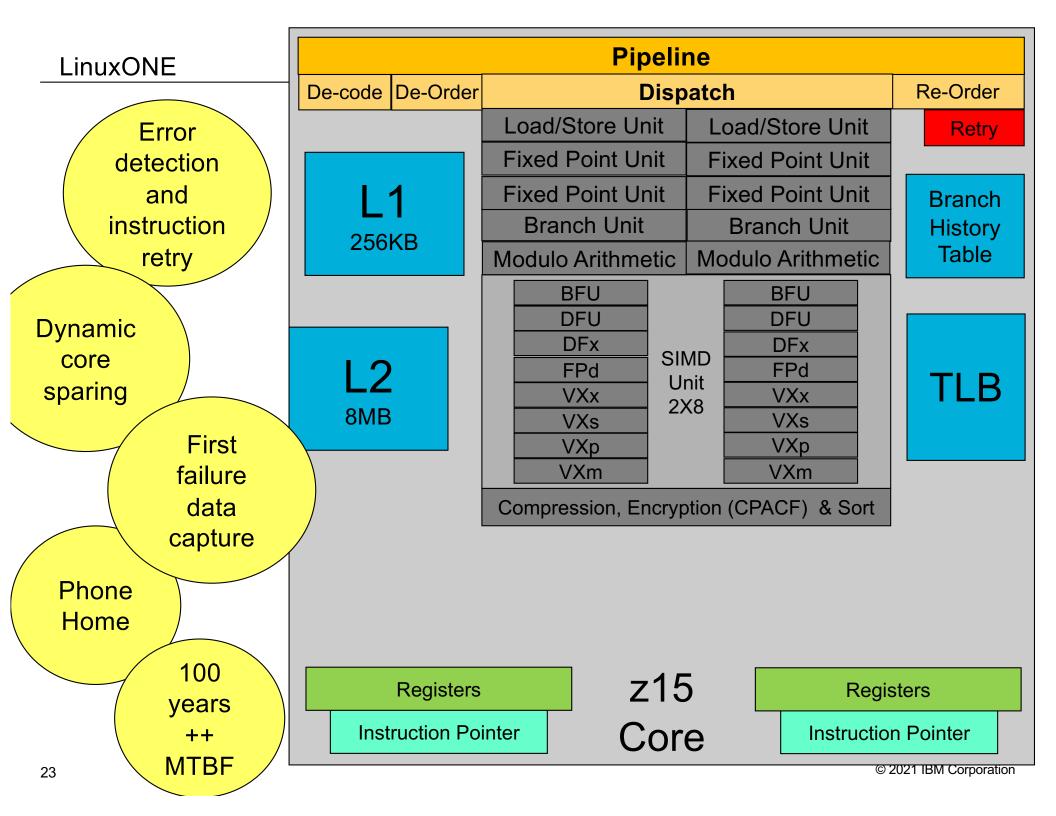


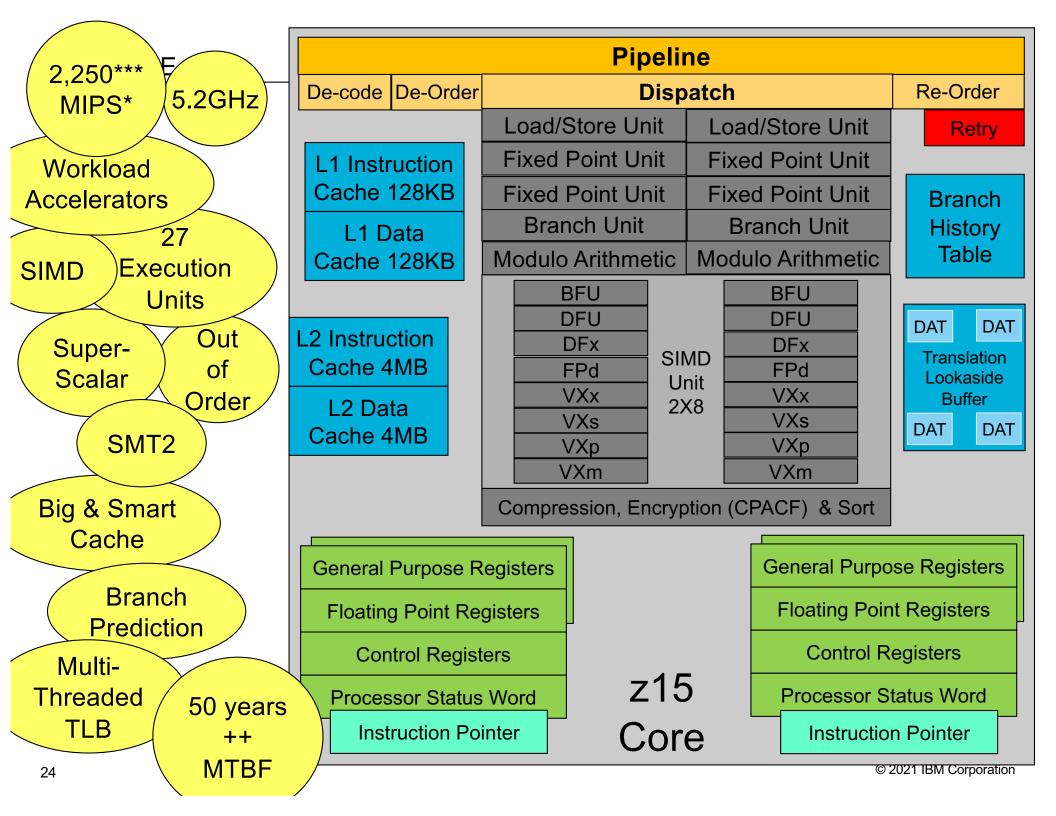








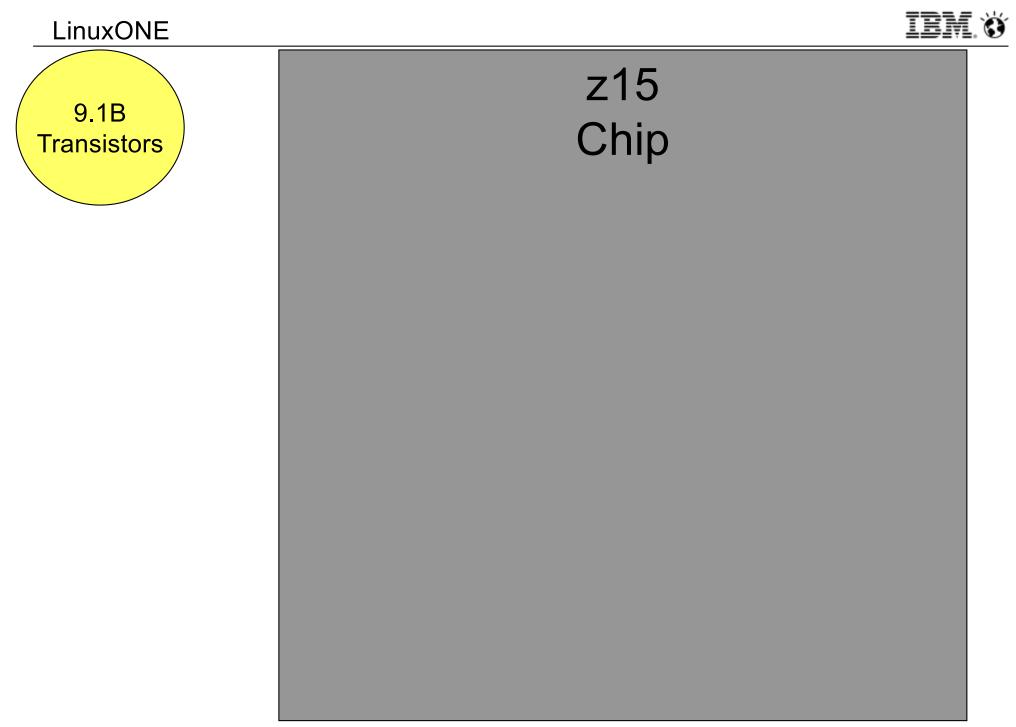




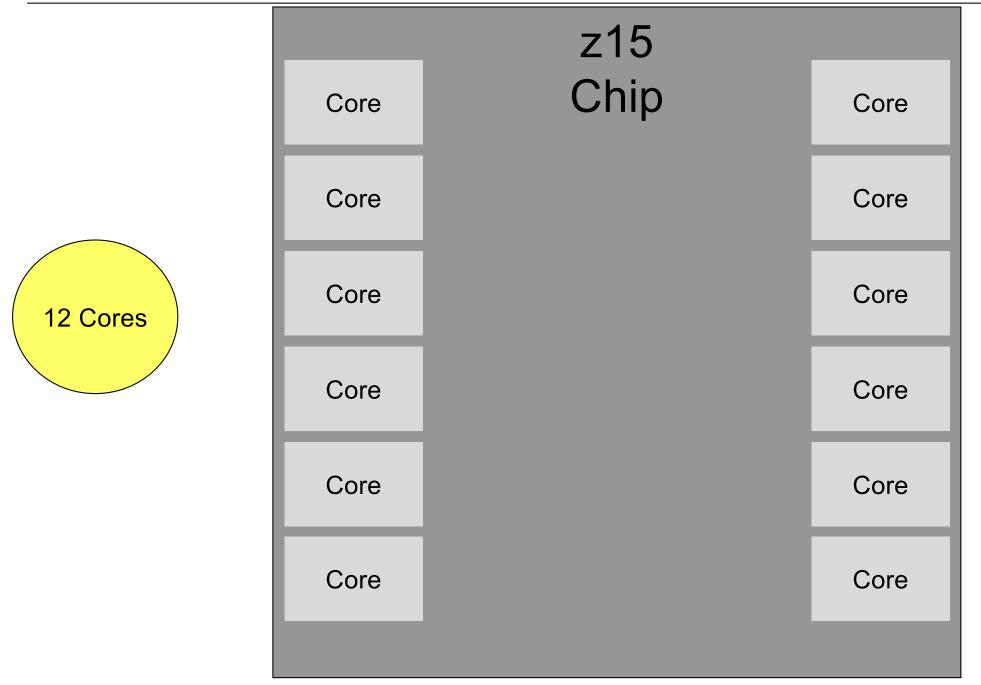


Cores to Chips 9 Billion Things to Like...

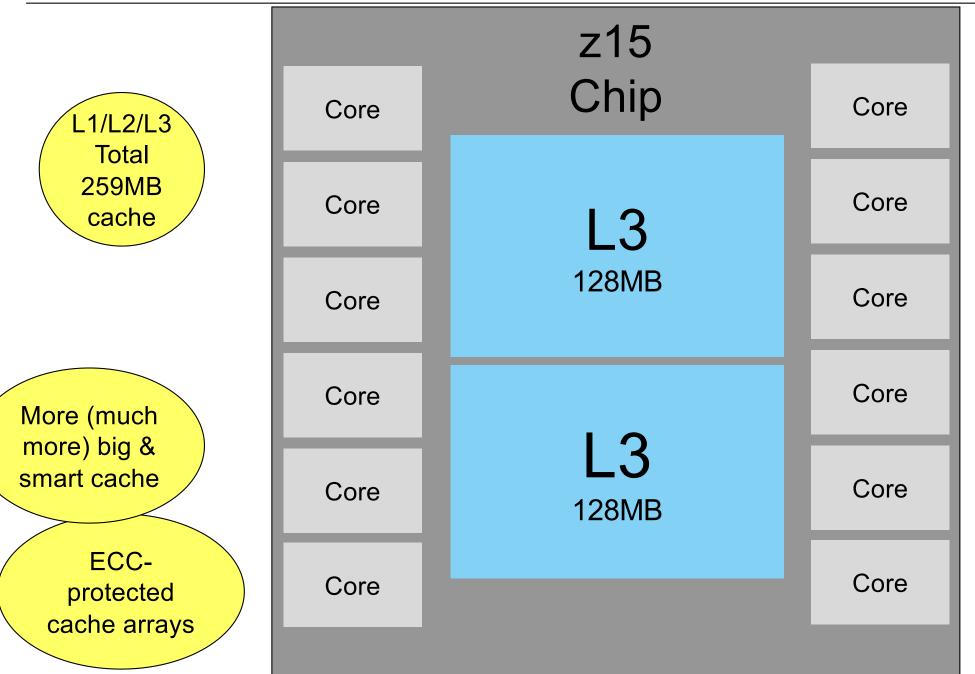
## THE Z15 CHIP





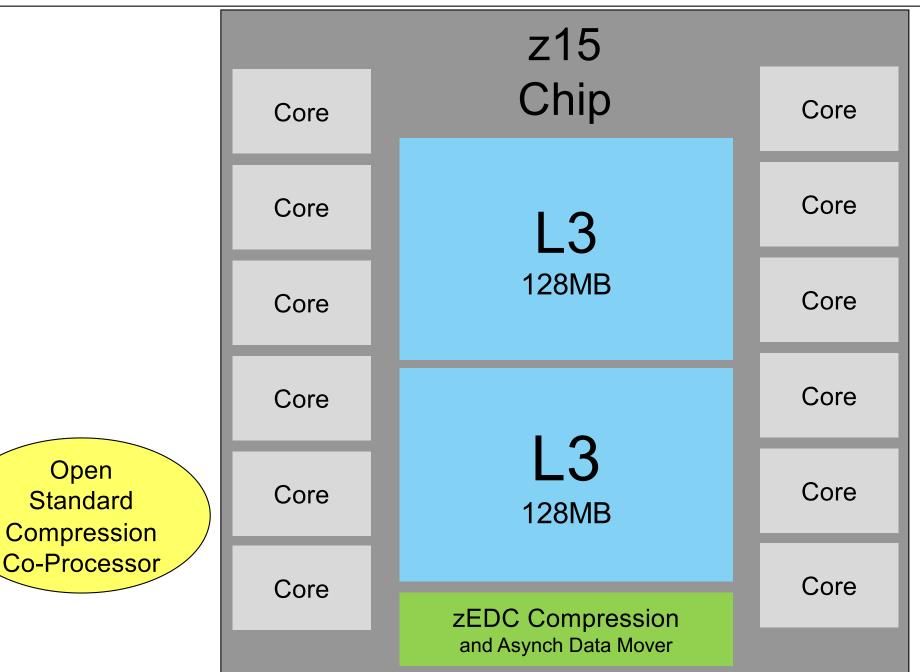




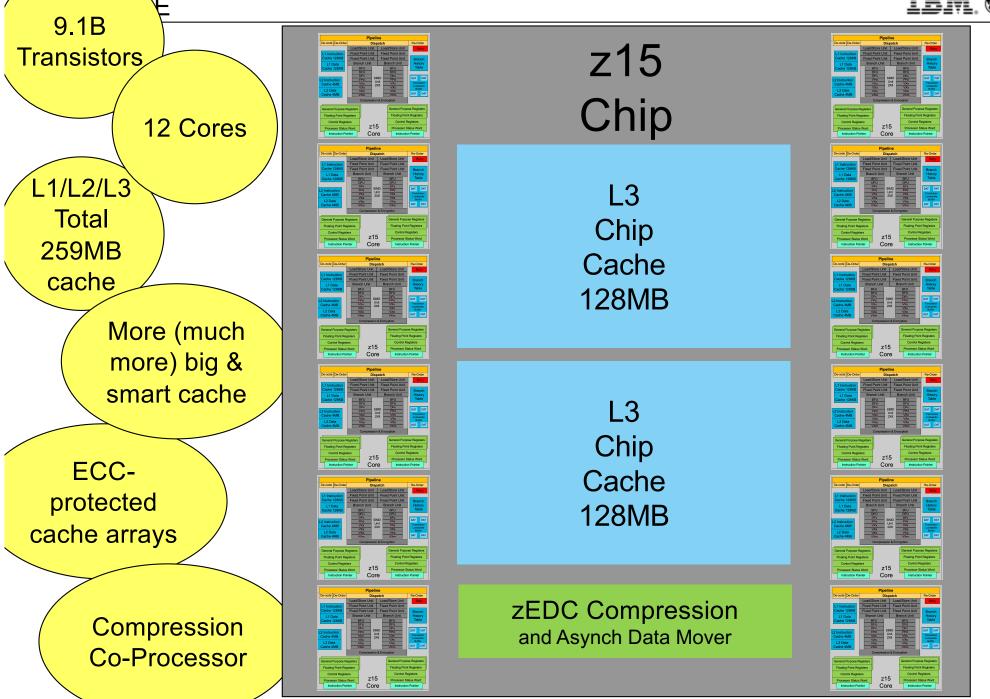


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Chips to Drawers

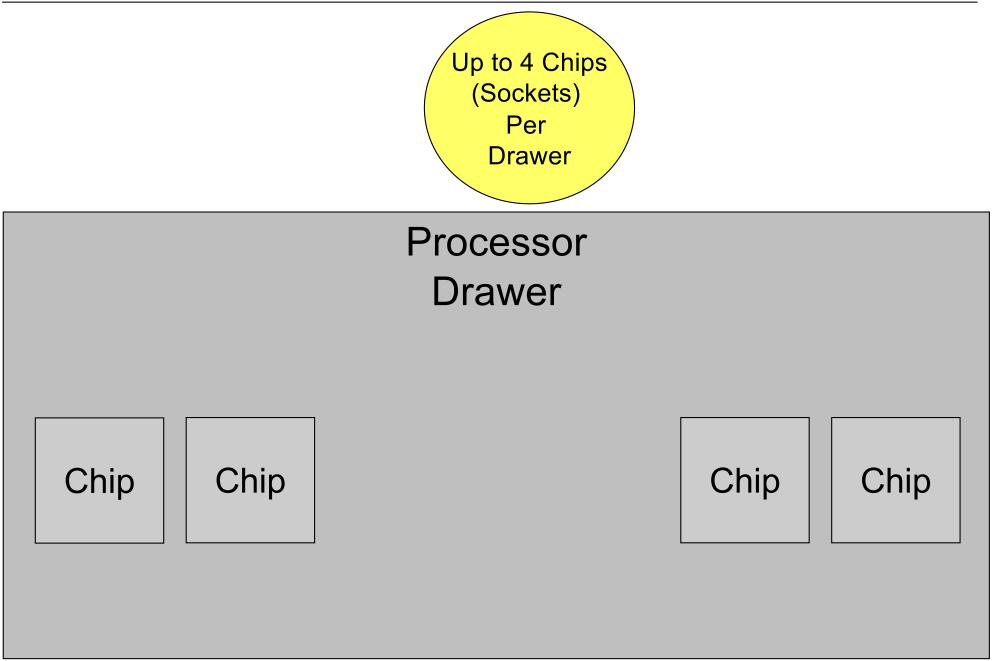
# THE LINUXONE III DRAWER

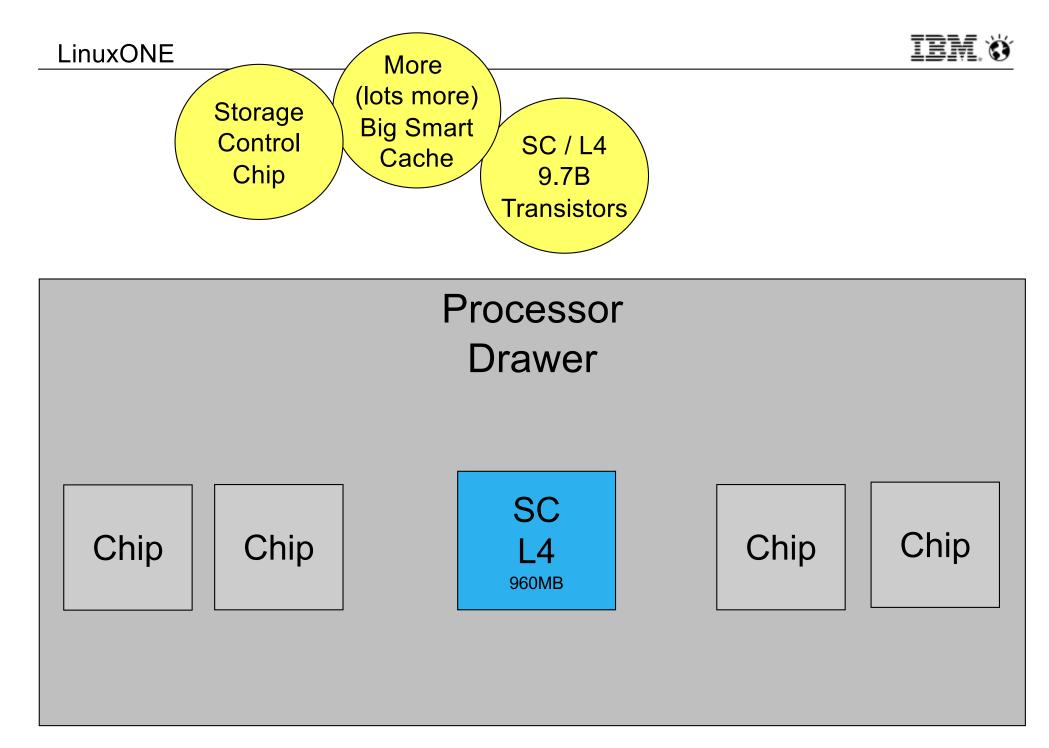


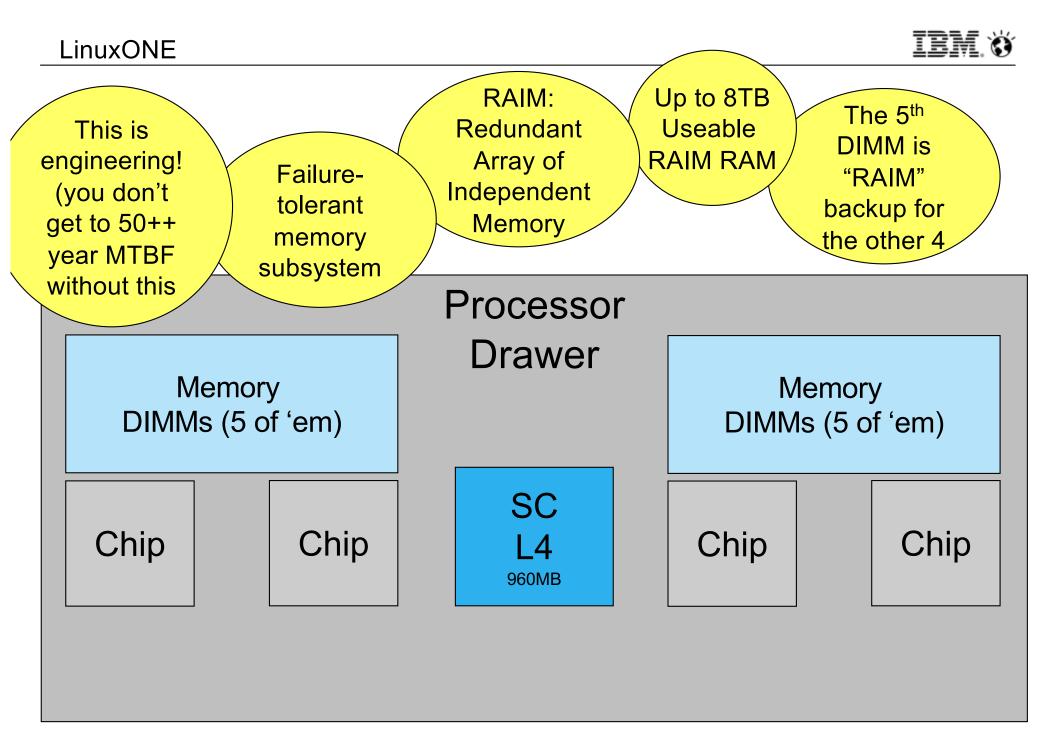


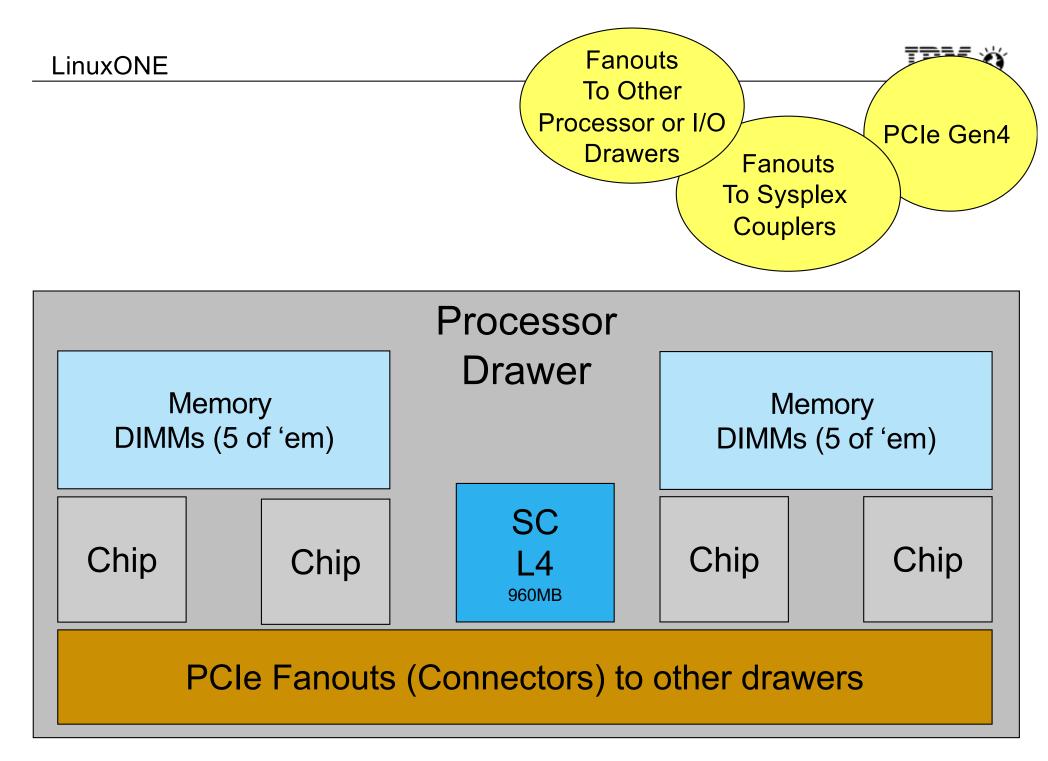
## Processor Drawer

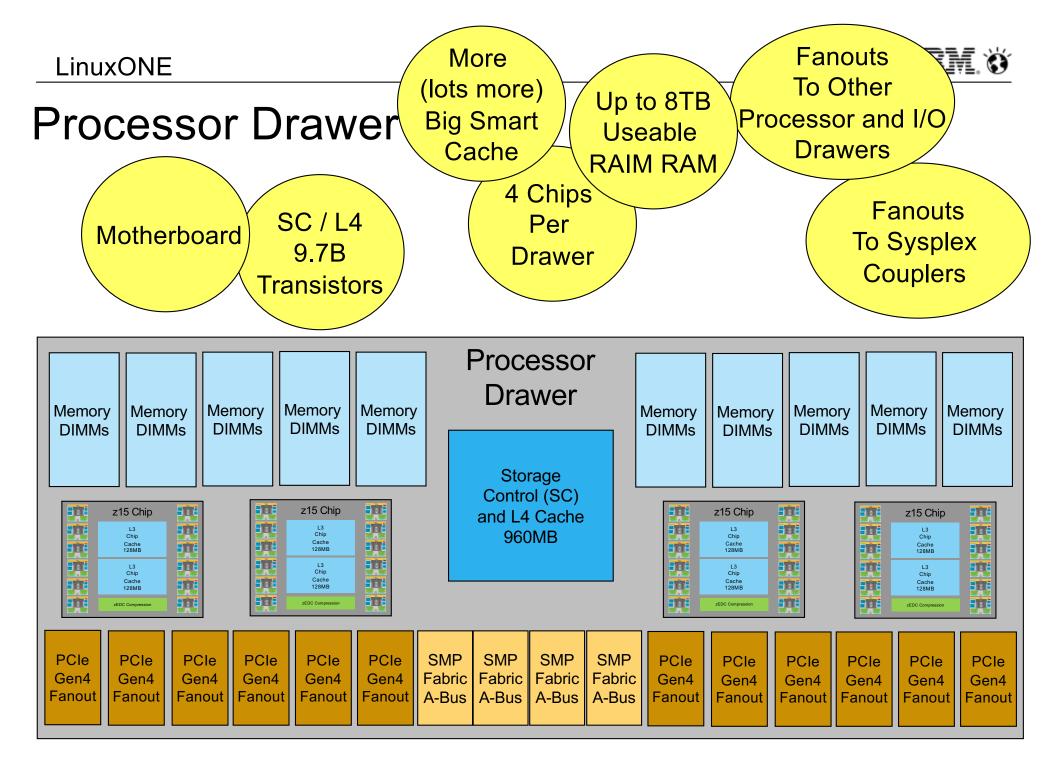














Drawers to CEC CEC: Central Electronics Complex The Processor Nest

# THE LINUXONE III CEC



# The Big Guy THE LINUXONE III LT1 CEC

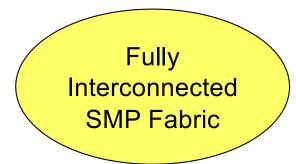


LT1 Model	Drawers	Cores	Memory (RAIM)
Max34	1	1 to 34	Up to 8TB

#### **Processor Drawer**

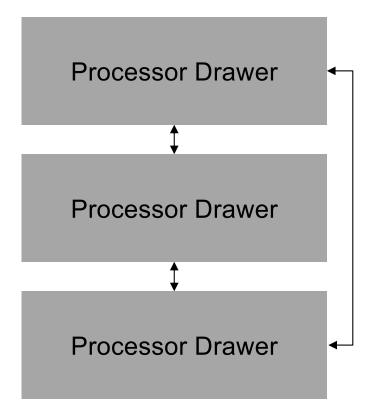


LT1 Model	Drawers	Cores	Memory (RAIM)
Max71	2	1 to 71	Up to 16TB



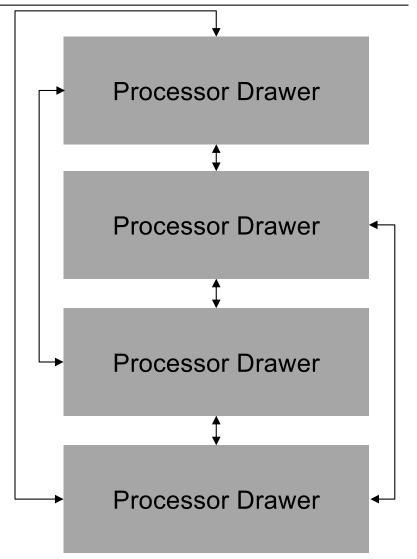
IBM. Ö

LT1 Model	Drawers	Cores	Memory (RAIM)
Max108	3	1 to 108	Up to 24TB

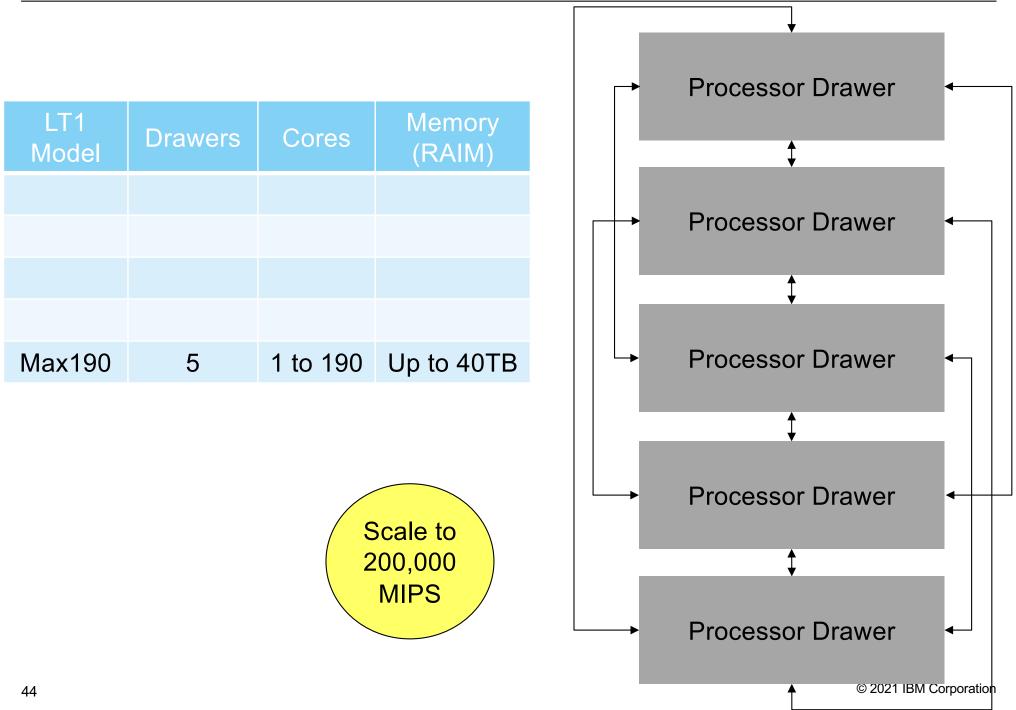


IBM. Ö

LT1 Model	Drawers	Cores	Memory (RAIM)
Max145	4	1 to 145	Up to 32TB

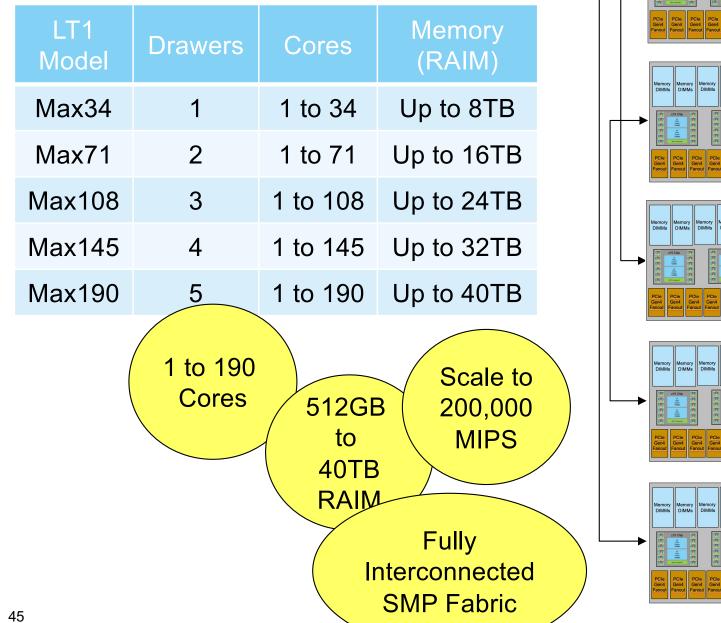


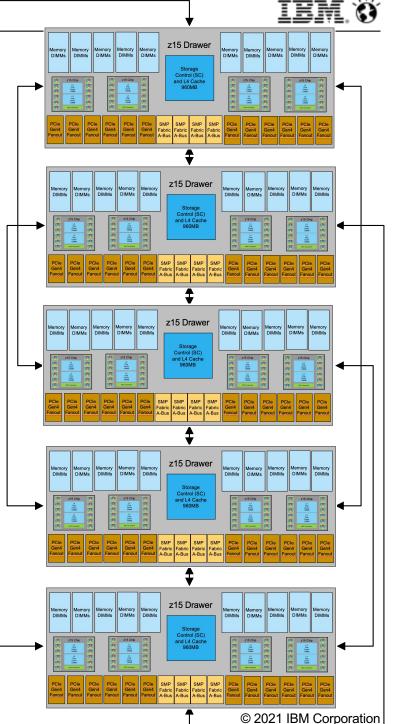
IBM. Ö



### LinuxONE

## CEC: LinuxONE III LT1







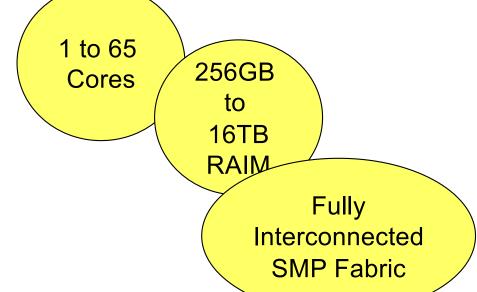
### The Little Guy

# THE LINUXONE III LT2 CEC

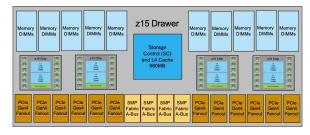
### IBM 🕉

# CEC: LinuxONE III LT2

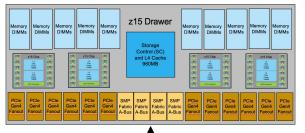
LT2 Model	Drawers	Cores	Memory (RAIM)
Max04	1	1 to 4	Up to 2TB
Max13	1	1 to 13	Up to 4TB
Max21	1	1 to 21	Up to 4TB
Max31	1	1 to 31	Up to 8TB
Max65	2	1 to 65	Up to 16TB

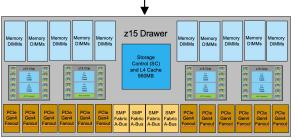


### Max04 Max13 Max21 Max31



#### Max65







Rack'em and Stack'em

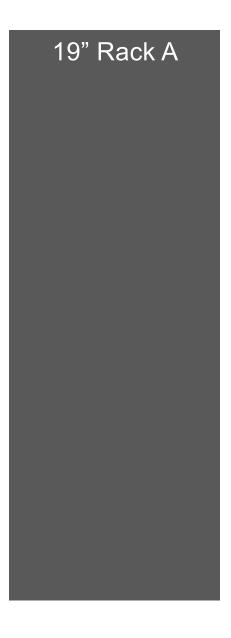
# THE LINUXONE III RACK(S)



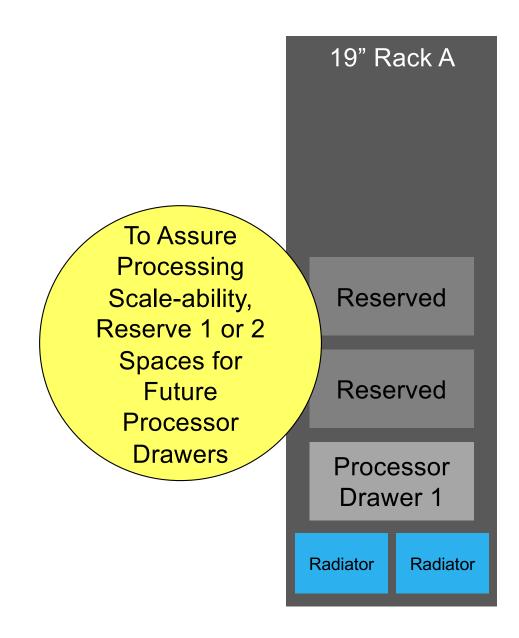
### Following...

- Following LinuxONE III LT1 server rack-buildout scenarios
  - and several LinuxONE III LT2 rack scenarios
- They are examples
- They illustrate key concepts
- There are many more

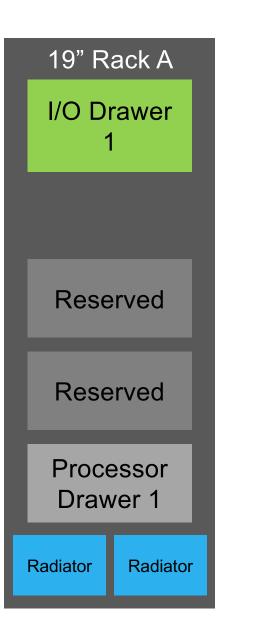






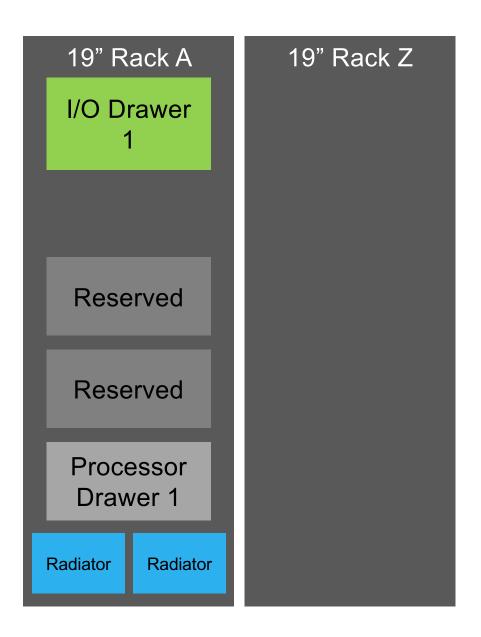


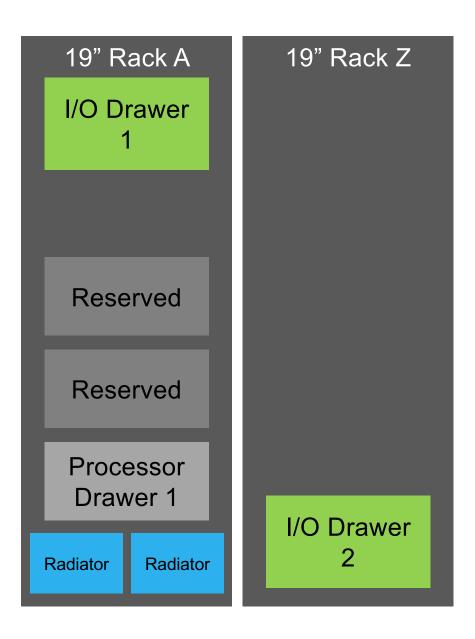


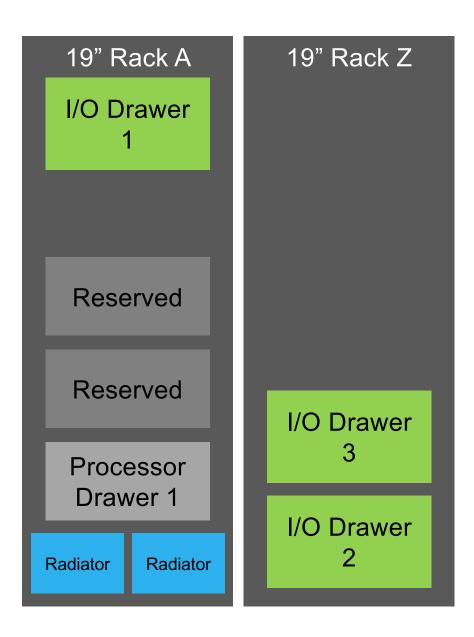


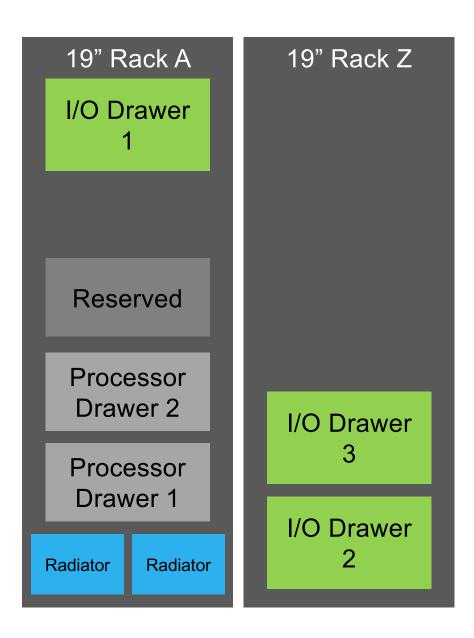


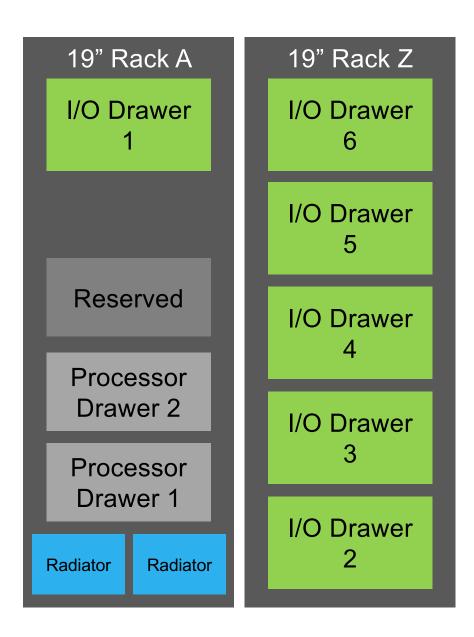
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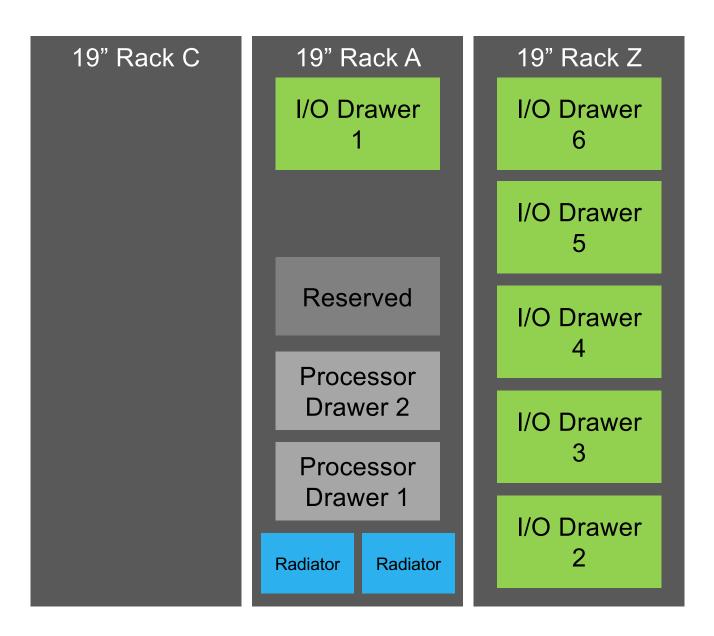


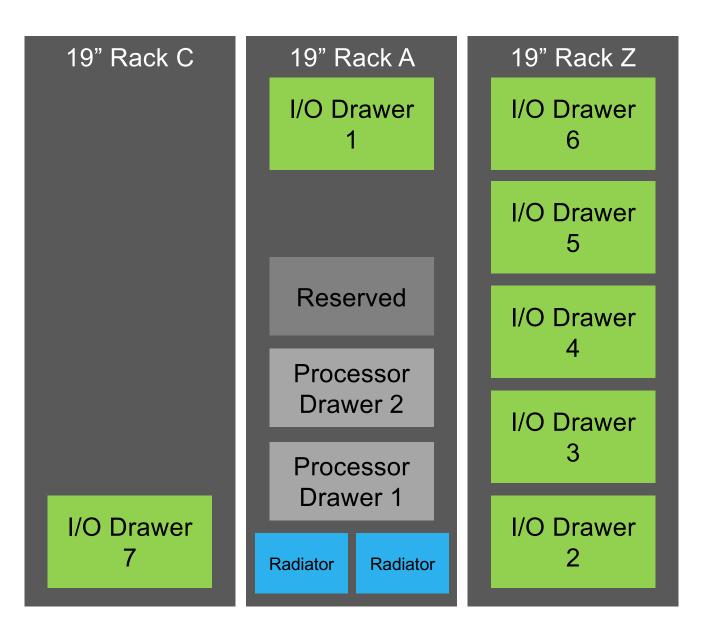




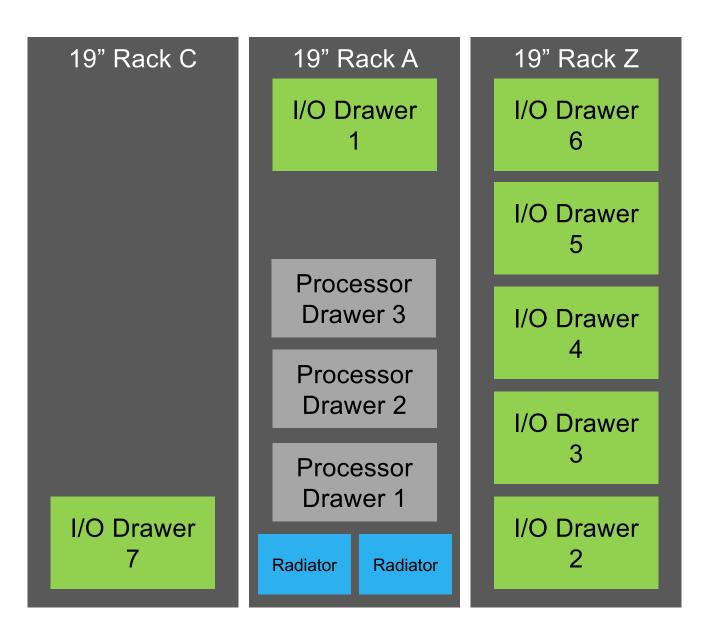


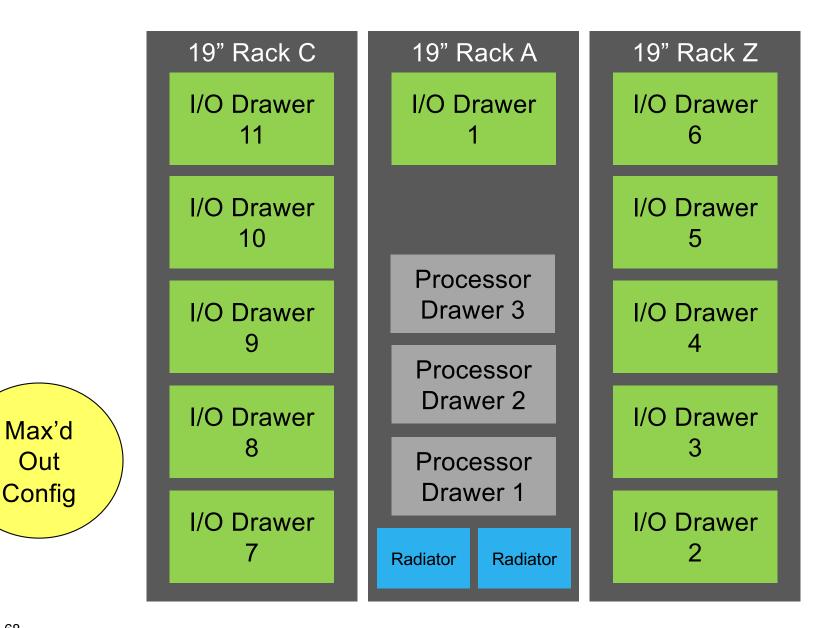






IEM





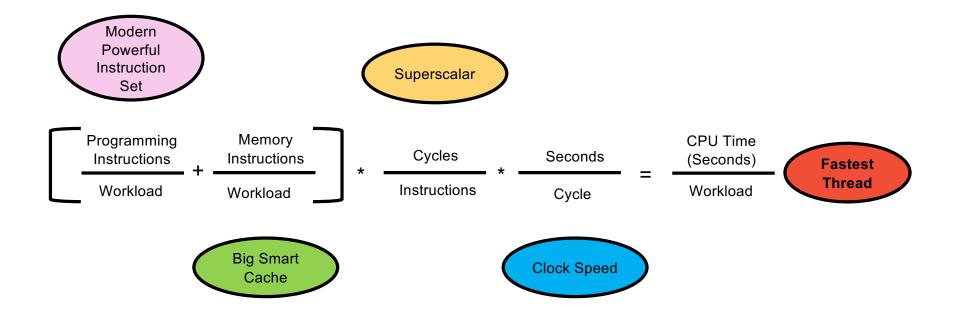
IEM



I'll Have Fries with That!

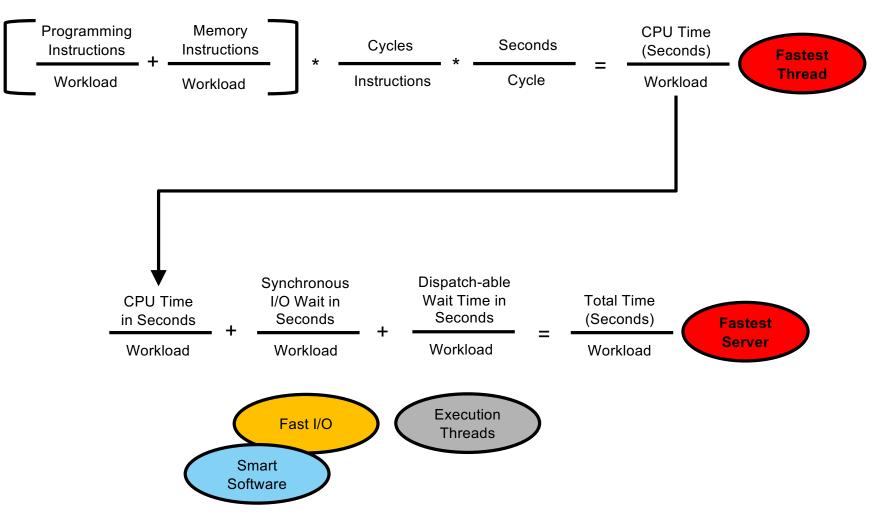
# THE SPECIAL SAUCE

# **Computer Science Core Performance**



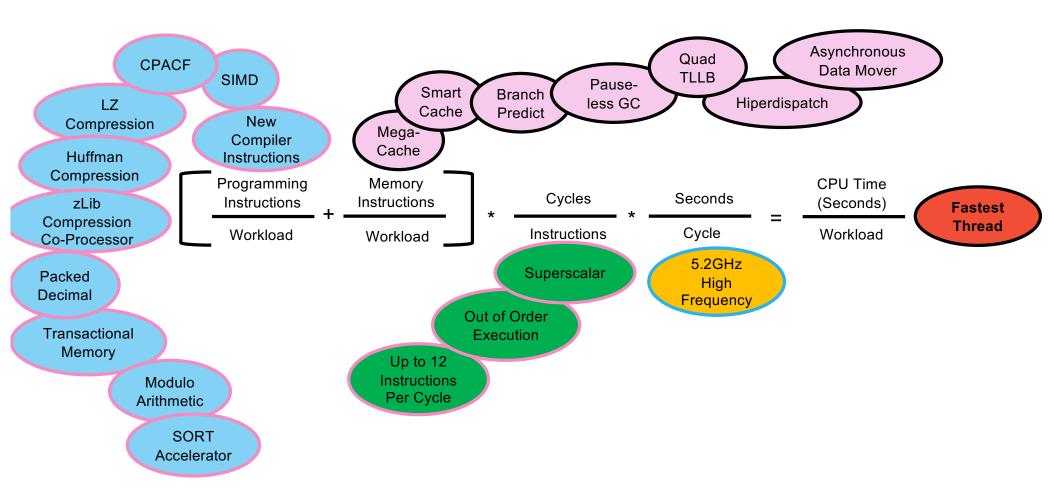


## **Computer Science Workload Performance**



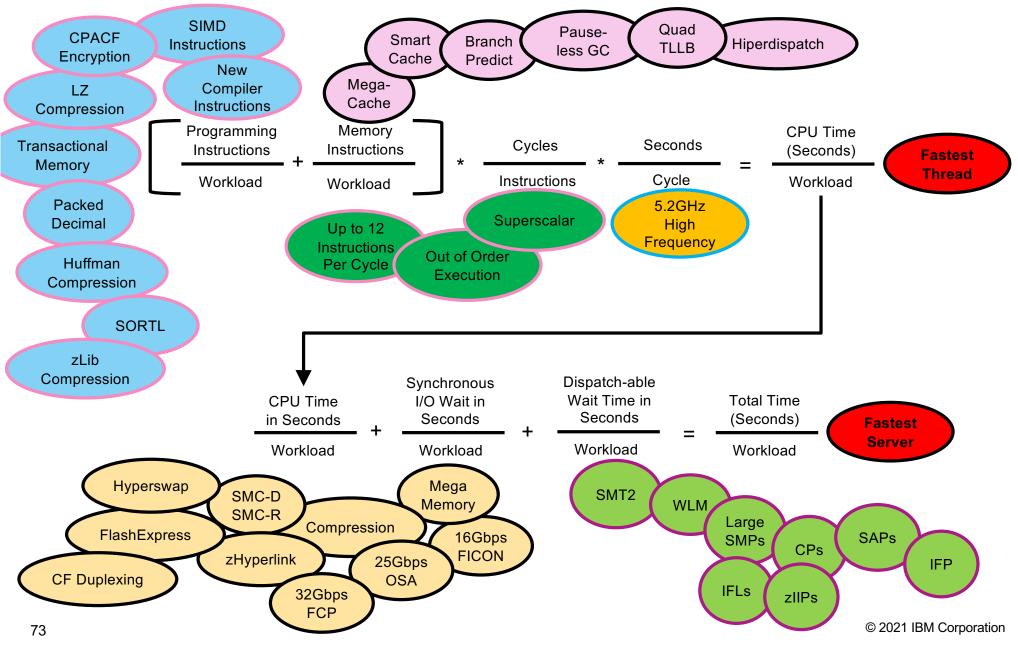


## **Computer Science Core Performance**





# **Computer Science Workload Performance**





## MIPS

- Millions of Instructions Per Second
- Mileage In-between Processing Systems
- Meaningless Information Per Second
- Meaningless Information Propagated by Sales-reps



### LSPR to the Rescue

- https://www-01.ibm.com/servers/resourcelink/lib03060.nsf/pages/lsprindex?OpenDocument
- Large Systems Performance Reference
  - The IBM Large System Performance Reference (LSPR) ratios represent IBM's assessment of relative processor capacity in an unconstrained environment for the specific benchmark workloads and system control programs specified in the tables. Ratios are based on measurements and analysis.
- A Capacity Planning Resource
- A Real(ish) set of Benchmarks for Mainframes
  - Almost certainly the best set of benchmarks in the industry
- zPCR z Processor Capacity Reference an Open Tool Full of LSPR Data & More
  - <u>https://www-03.ibm.com/support/techdocs/atsmastr.nsf/WebIndex/PRS1381</u>



# **Historical Look At MIPS**

Year	 d Party (/MIPS	MIPS per CORE	MIPS per CHIP	MIPS per BOARD (book or drawer or mcm)	Single Image MIPS	Notes	CORES per CHIP
1994	\$ 30.00	15	15	61	61	9672 G1	1
1995	\$ 20.00	22	22	186	186	9672 G2	1
1996	\$ 13.00	45	45	357	357	9672 G3	1
1997	\$ 9.00	63	63	446	446	9672 G4	1
1998	\$ 5.50	117	117	1,069	1,069	9672 G5 Turbo	1
1999	\$ 3.50	176	176	1,606	1,606	9672 G6 Turbo	1
2000	\$ 2.50	235	235	765	3,061	z900 1Cs	1
2001	\$ 2.40	235	235	765	3,061		1
2002	\$ 2.20	278	278	1,091	3,804	z900 2Cs	1
2003	\$ 2.00	443	876	1,715	11,391	z990	1
2004	\$ 2.00	443	876	1715	11391		1
2005	\$ 2.00	443	876	1715	11391		1
2006	\$ 1.80	600	2,317	8,271	23,716	z9	2
2007	\$ 1.50	600	2,317	8,271	23,716		2
2008	\$ 1.40	990	3,701	10,177	43,426	z10	4
2009	\$ 1.30	990	3,701	10,177	43,426		4
2010	\$ 1.00	1,280	4,833	16,289	68,410	z196	4
2011	\$ 1.00	1,280	4,833	16,289	68,410		4
2012	\$ 1.00	1,650	9,097	26,604	103,699	zEC12	6
2013	\$ 1.00	1,650	9,097	26,604	103,699		6
2014	\$ 1.00	1,650	9,097	26,604	103,699		6
2015	\$ 1.00	1,906	13,627	43,269	154,904	z13	8
2016	\$ 1.00	1,906	13,627	43,269	154,904		8
2017	\$ 1.00	2,020	17,783	50,521	195,496	z14	10
2018	\$ 1.00	2,020	17,783	50,521	195,496		10
2019	\$ 1.00	2,232	23,414	58,197	240,718	z15	12

# CMOS MIPSTORY

LinuxONE



----

990

3,701

10,177 43,426

1,280 4,833 16,289 68,410

1,650 9,097 26,604 103,699

1,906 13,627 43,269 154,904

2,020 17,783 50,521 195,496

2,232 23,414 58,197 240,718

#### 9 CMOS Generations of IBM Z CORES and CHIPS and Drawers

1 z/OS-2.3 LSPR zPCR V9.3 CEC 2097-7xx 164 64W IFL   2 LSPR Multi-Image Capacity Ratios CORE 2817-7xx 11 1W IFL   3 IBM Z IFL CPs CORE 2817-7xx 14 4W IFL   4 Values are representative of z/VM, KVM, CEC 2817-7xx 14 4W IFL   5 Capacity basis: 2827-701 @ 1,650.0 MIPS CEC 2817-7xx 180 80W IFL   6 Capacity for z/OS on z10 and later process CEC 2817-7xx 164 64W IFL   7 CEC 2817-7xx 180 80W IFL 2827-7xx 180 80W IFL   2 EC 2827-7xx 164 64W IFL 2664 2827-7xx 164 64W IFL   2 900 z900 Turbo CEC 2827-7xx 164 64W IFL   2 900 2900 Turbo CEC 2827-7xx 164 64W IFL   2 900 2900 Turbo CEC 2827-7xx 164 64W IFL   2 900 2900 Turbo 213 213/700 CEC 2827-7xx 164 64W IFL   2 900 29064-2Cx 115 15W IFL 3,804					BOARD	2097-7XX 112	12VV IFL
2 LSPR Multi-Image Capacity Ratios   3 IBM Z IFL CPs   4 Values are representative of z/VM, KVM,   5 Capacity basis: 2827-701 @ 1,650.0 MIPS   6 Capacity for z/OS on z10 and later process   9 CORE 2817-7xx 115 15W IFL   9 CORE 2817-7xx 108 80W IFL   2EC12 2EC12/700 CORE 2827-7xx 16 6W IFL   9 ELow CORE 2827-7xx 16 6W IFL   9 ELow CORE 2827-7xx 10 101W IFL   2900 z900 Turbo CORE 2827-7xx 10 101W IFL   21390 2900 Turbo CORE 2827-7xx 10 101W IFL   2900 2900 Turbo CORE 2827-7xx 10 101W IFL   213700 CORE 2064-2Cx 11 1W IFL 1,091   CEC 2064-2Cx 11 1W IFL 3,804 BOARD 2964-7xx 18 8W IFL   2990 2990/300 CCCE 2964-7xx 130 30W IFL 214 214/700   CORE 2084-3xx 12 2W IFL 876 CORE <td>1</td> <td>-/06 3 3 1 600</td> <td>-DCD VO 2</td> <td></td> <td>CEC</td> <td>2097-7xx 164</td> <td>64W IFL</td>	1	-/06 3 3 1 600	-DCD VO 2		CEC	2097-7xx 164	64W IFL
3 IBM Z IFL CPs CHIP 2817-7xx I4 4W IFL   4 Values are representative of z/VM, KVM, BOARD 2817-7xx I4 4W IFL   5 Capacity basis: 2827-701 @ 1,650.0 MIPs CEC 2817-7xx I80 80W IFL   6 Capacity for z/OS on z10 and later process CORE 2827-7xx I0 80W IFL   9 CORE 2827-7xx I6 6W IFL   9 COW CORE 2827-7xx I0 20W IFL   2900 z900 Turbo CCIIP 2827-7xx I0 20W IFL   CHIP 2064-2Cx I1 1W IFL 278 CORE 2827-7xx I0 20W IFL   CARD 2064-2Cx I1 1W IFL 1,091 CORE 2964-7xx I1 1W IFL   CARE 2064-2Cx I15 15W IFL 3,804 BOARD 2964-7xx I8 8W IFL   CORE 2084-3xx I1 1W IFL 443 CHIP 2964-7xx I30 30W IFL   CORE 2084-3xx I2 2W IFL 876 CORE 3906-7xx I10 10W IFL   BOARD 2084-3xx I2 2W IFL 1,391 CCRE 3906-7xx I10 <t< td=""><td></td><td></td><td></td><td>-</td><td>z196</td><td>z196/700</td><td></td></t<>				-	z196	z196/700	
A Values are representative of z/VM, KVM,   5 Capacity basis: 2827-701 @ 1,650.0 MIPS   6 Capacity for z/OS on z10 and later process   7 6   8 Processor   9 Correction   9 Correction   2900 2900 Turbo   CHIP 2064-2Cx 11   11 11W IFL   2900 2064-2Cx 11   12900 2900 Turbo   CHIP 2064-2Cx 11   11 11W IFL   2900 2900/300   CORE 2064-2Cx 115   15W IFL 3,804   BOARD 2064-2Cx 115   15W IFL 3,804   BOARD 2064-2Cx 115   15W IFL 3,804   BOARD 2064-3xx 11   CORE 2064-7xx 18   800 IFL 2064-7xx 11   CORE 2064-7xx 11   CORE 2064-7xx 11   CORE 2064-7xx 130   CORE 2064-7xx 14   CHIP 2064-7xx 131   DARD 2084-3xx 12   <	2	LSPR Multi-Ima	age Capacity	Ratios	CORE	2817-7xx I1	1W IFL
4 Values are representative of 2/ VM, KVM,   5 Capacity basis: 2827-701 @ 1,650.0 MIPS   6 Capacity for z/OS on z10 and later process   8 Processor   9 CORE   2900 z900 Turbo   CHIP 2827-7xx 16   6 Gapacity for z/OS on z10 and later process   9 CORE   9 Low   CHIP 2827-7xx 16   6 WIFL   2900 z900 Turbo   CHIP 2064-2Cx 11   10W IFL 278   CORE 2964-7xx 11   11W IFL 3,804   BOARD 2064-2Cx 115   15W IFL 3,804   BOARD 2964-7xx 118   2064-2Cx 115 15W IFL   3,804 BOARD   2990 z990/300   CORE 2064-7xx 114   CHIP 2084-3xx 12   2W IFL 876   CORE 3906-7xx 110   BOARD 2084-3xx 132   32W IFL 11,391   cEC 2084-3xx 132	3	IBM Z IFL CPs			CHIP	2817-7xx 14	4W IFL
5 Capacity basis: 2827-701 @ 1,650.0 MIPS CEC 2817-7xx 180 80W IFL   6 Capacity for z/OS on z10 and later process ZEC12 ZEC12 ZEC12/700   7 9 CORE 2827-7xx 11 1W IFL   9 Low CORE 2827-7xx 120 20W IFL   2900 2900 Turbo Low CEC 2827-7xx 120 20W IFL   CHIP 2064-2Cx 11 1W IFL 278 CORE 2827-7xx 110 101W IFL   BOARD 2064-2Cx 14 4W IFL 1,091 CORE 2964-7xx 130 30W IFL   2900 z'990/300 TURD CORE 2964-7xx 130 30W IFL   2900 z'990/300 CCCE 2964-7xx 130 30W IFL   CORE 2084-3xx 11 1W IFL 443 CHIP 2964-7xx 130 30W IFL   CHIP 2084-3xx 12 2W IFL 876 CORE 3906-7xx 111 1W IFL   BOARD 2084-3xx 132 32W IFL 11,391 CHIP 3906-7xx 110 10W IFL   29 EC z9 EC/700 TUR 600 CORE <t< td=""><td>4</td><td>Values are rep</td><td>resentative o</td><td>fz/VM. KVM</td><td>BOARD</td><td>2817-7xx 115</td><td>15W IFL</td></t<>	4	Values are rep	resentative o	fz/VM. KVM	BOARD	2817-7xx 115	15W IFL
6   Capacity for z/OS on z10 and later process   CORE   2827-7xx 11   1W IFL     8   Processor   Features   CORE   2827-7xx 16   6W IFL     9   Low   CORE   2827-7xx 10   101W IFL     2900   z900 Turbo   Low   CEC   2827-7xx 11   1W IFL     BOARD   2064-2Cx 11   1W IFL   278   CORE   2964-7xx 11   1W IFL     CEC   2064-2Cx 115   15W IFL   3,804   CORE   2964-7xx 130   30W IFL     CORE   2084-3xx 11   1W IFL   443   CEC   2964-7xx 130   30W IFL     CORE   2084-3xx 12   2W IFL   876   CORE   3906-7xx 11   1W IFL     BOARD   2084-3xx 132   32W IFL   1,715   CORE   3906-7xx 110   10W IFL     z9 EC   z9 EC/700   Z15   z15/700   CORE   3906-7xx 111   1W IFL     CHIP   2094-7xx 14   4W IFL   2,317   CEC   3906-7xx 111   1W IFL     CORE   2094-7xx 116 <td></td> <td></td> <td></td> <td></td> <td>CEC</td> <td>2817-7xx 180</td> <td>80W IFL</td>					CEC	2817-7xx 180	80W IFL
8   Processor   Features     9   Low   2827-7xx 16   6W IFL     2900   2900 Turbo   2000 Turbo   2827-7xx 120   20W IFL     CHIP   2064-2Cx 11   1W IFL   278   CCRE   2827-7xx 1101   101W IFL     BOARD   2064-2Cx 14   4W IFL   1,091   CCRE   2964-7xx 18   8W IFL     CEC   2064-2Cx 115   15W IFL   3,804   CHIP   2964-7xx 18   8W IFL     CORE   2064-3xx 11   1W IFL   443   CEC   2964-7xx 130   30W IFL     CORE   2084-3xx 11   1W IFL   443   214   214/700   2064-7xx 111   141W IFL     CORE   2084-3xx 12   2W IFL   876   CORE   3906-7xx 111   1W IFL     BOARD   2084-3xx 132   32W IFL   1,715   BOARD   3906-7xx 110   10W IFL     29 EC   29 EC/700   2094-7xx 14   4W IFL   2,317   CEC   3906-7xx 1170   170W IFL     215   215/700   CORE					2012	zEC12/700	
BOARD   2827-7xx 120   20W IFL     2900   z900 Turbo   2004-2Cx 11   1W IFL   278     BOARD   2064-2Cx 11   1W IFL   278   CORE   2964-7xx 11   1W IFL     BOARD   2064-2Cx 14   4W IFL   1,091   CHIP   2964-7xx 18   8W IFL     CEC   2064-2Cx 115   15W IFL   3,804   BOARD   2964-7xx 130   30W IFL     Z990   z990/300	6	Capacity for z/	OS on z10 and	d later process		2827-7xx  1	1W IFL
9   CEC   2827-7xx I101   101W IFL     2900   2900 Turbo   213   213/700     CHIP   2064-2Cx I1   1W IFL   278     BOARD   2064-2Cx I4   4W IFL   1,091     CEC   2064-2Cx I15   15W IFL   3,804     CEC   2064-2Cx I15   15W IFL   3,804     CP00   2990/300   2964-7xx I8   8W IFL     CORE   2084-3xx I1   1W IFL   443     CORE   2084-3xx I2   2W IFL   876     BOARD   2084-3xx I2   2W IFL   11,391     CEC   2084-3xx I32   32W IFL   11,391     Z9 EC   29 EC/700   2084-7xx I1   1W IFL     CORE   2094-7xx I1   1W IFL   600     CORE   2094-7xx I1   1W IFL   2,317     CORE   2094-7xx I4   4W IFL   2,317     CORE   2094-7xx I4   4W IFL   2,317     CHIP   2094-7xx I16   16W IFL   8,271     BOARD   2094-	8	Processor	Features				
Z900   Z900 Turbo   CEC   2827-7xx 1101   101W IFL     Z900   Z900 Turbo   Z13   Z13/700   CORE   2964-7xx 11   1W IFL     BOARD   2064-2Cx 14   4W IFL   1,091   CORE   2964-7xx 18   8W IFL     CEC   2064-2Cx 115   15W IFL   3,804   2964-7xx 18   8W IFL     CEC   2064-3xx 11   1W IFL   443   CEC   2964-7xx 141   141W IFL     CORE   2084-3xx 12   2W IFL   876   CORE   3906-7xx 11   1W IFL     BOARD   2084-3xx 12   2W IFL   1,715   CORE   3906-7xx 11   1W IFL     CEC   2084-3xx 132   32W IFL   11,391   CHIP   3906-7xx 110   10W IFL     CEC   2084-3xx 132   32W IFL   11,391   CEC   3906-7xx 110   10W IFL     CEC   2084-3xx 132   32W IFL   11,391   CEC   3906-7xx 110   10W IFL     CORE   2094-7xx 11   1W IFL   2,317   CEC   3906-7xx 110   10W IFL	9			Low			
CHIP   2064-2Cx I1   1W IFL   278     BOARD   2064-2Cx I4   4W IFL   1,091     CEC   2064-2Cx I15   15W IFL   3,804     z990   z990/300   z964-7xx I30   30W IFL     CORE   2084-3xx I1   1W IFL   443     CHIP   2084-3xx I2   2W IFL   876     BOARD   2084-3xx I2   2W IFL   876     BOARD   2084-3xx I32   32W IFL   1,715     CEC   2084-3xx I32   32W IFL   11,391     z9 EC   z9 EC/700   2094-7xx I1   1W IFL     CORE   2094-7xx I1   1W IFL   2,317     CORE   2094-7xx I1   1W IFL   1,715     CEC   2084-3xx I32   32W IFL   11,391     z9 EC   z9 EC/700   2094-7xx I1   1W IFL     CORE   2094-7xx I1   1W IFL   2,317     CORE   2094-7xx I1   1W IFL   2,317     CORE   2094-7xx I1   1W IFL   2,317     CORE	-	7900 Turbo					101W IFL
BOARD 2064-2Cx I4 4W IFL 1,091   CEC 2064-2Cx I15 15W IFL 3,804   Z990 Z990/300 CEC 2964-7xx I8 8W IFL   CORE 2084-3xx I1 1W IFL 443 CEC 2964-7xx I14 141W IFL   CORE 2084-3xx I2 2W IFL 876 CEC 2964-7xx I11 1W IFL   BOARD 2084-3xx I2 2W IFL 876 CORE 3906-7xx I11 1W IFL   BOARD 2084-3xx I32 32W IFL 1,715 CEC 3906-7xx I10 10W IFL   BOARD 2084-3xx I32 32W IFL 11,391 CEC 3906-7xx I10 10W IFL   Z9 EC Z9 EC/700 CEC 3906-7xx I170 170W IFL   CORE 2094-7xx I1 1W IFL 600 CEC 3906-7xx I170 170W IFL   CHIP 2094-7xx I1 1W IFL 600 CEC 3906-7xx I170 170W IFL   CHIP 2094-7xx I1 1W IFL 2,317 600 CORE 8561-7xx I1 1W IFL   BOARD 2094-7xx I16 16W IFL 8,2				070			
CEC 2064-2Cx I15 15W IFL 3,804 BOARD 2964-7xx I30 30W IFL   2990 2990/300 CEC 2964-7xx I30 30W IFL CEC 2964-7xx I30 30W IFL   CORE 2084-3xx I1 1W IFL 443 CHIP 2084-3xx I2 2W IFL 876   BOARD 2084-3xx I2 2W IFL 876 CORE 3906-7xx I1 1W IFL   BOARD 2084-3xx I32 32W IFL 1,715 CCRE 3906-7xx I10 10W IFL   CEC 2084-3xx I32 32W IFL 11,391 CEC 3906-7xx I10 10W IFL   Z9 EC 29 EC/700 CORE 2094-7xx I1 1W IFL 600 CEC 3906-7xx I170 170W IFL   CHIP 2094-7xx I1 1W IFL 2,317 600 CORE 8561-7xx I1 1W IFL   CHIP 2094-7xx I16 16W IFL 8,271 BOARD 8561-7xx I34 34W IFL							1W IFL
Z990   Z990/300   CEC   2964-7xx I141   141W IFL     CORE   2084-3xx I1   1W IFL   443   214   214/700     CHIP   2084-3xx I2   2W IFL   876   CORE   3906-7xx I1   1W IFL     BOARD   2084-3xx I4   4W IFL   1,715   CORE   3906-7xx I10   10W IFL     CEC   2084-3xx I32   32W IFL   11,391   BOARD   3906-7xx I10   10W IFL     Z9 EC   Z9 EC/700   CORE   2094-7xx I1   1W IFL   600   CORE   3906-7xx I170   170W IFL     CORE   2094-7xx I1   1W IFL   2,317   CEC   3906-7xx I11   1W IFL     BOARD   2094-7xx I16   16W IFL   8,271   CORE   8561-7xx I12   12W IFL     BOARD   2094-7xx I16   16W IFL   8,271   BOARD   8561-7xx I34   34W IFL					CHIP	2964-7xx 18	8W IFL
CORE   2084-3xx I1   1W IFL   443     CHIP   2084-3xx I2   2W IFL   876     BOARD   2084-3xx I4   4W IFL   1,715     CEC   2084-3xx I32   32W IFL   11,391     z9 EC   z9 EC/700   2094-7xx I1   1W IFL     CORE   2094-7xx I1   1W IFL   600     CHIP   2094-7xx I4   4W IFL   2,317     BOARD   2094-7xx I16   16W IFL   8,271	CEC	2064-2Cx 115	15W IFL	3,804	BOARD	2964-7xx 130	30W IFL
CHIP   2084-3xx I2   2W IFL   876     BOARD   2084-3xx I4   4W IFL   1,715     CEC   2084-3xx I32   32W IFL   11,391     z9 EC   z9 EC/700   CCRE   3906-7xx I10   10W IFL     CORE   2094-7xx I1   1W IFL   600   CCRE   3906-7xx I170   170W IFL     CORE   2094-7xx I1   1W IFL   600   CCRE   3906-7xx I170   170W IFL     CORE   2094-7xx I1   1W IFL   600   CORE   8561-7xx I1   1W IFL     BOARD   2094-7xx I16   16W IFL   2,317   CHIP   8561-7xx I12   12W IFL     BOARD   2094-7xx I16   16W IFL   8,271   BOARD   8561-7xx I34   34W IFL	z990	z990/300			2010/01		141W IFL
CHIT   2004-5XX 12   2W ITE   600     BOARD   2084-3xx 14   4W IFL   1,715     CEC   2084-3xx 132   32W IFL   11,391     z9 EC   z9 EC/700   11,391   CEC   3906-7xx 133   33W IFL     CORE   2094-7xx 11   1W IFL   600   CEC   3906-7xx 110   170W IFL     CORE   2094-7xx 11   1W IFL   600   CORE   3906-7xx 110   170W IFL     CHIP   2094-7xx 11   1W IFL   600   CORE   8561-7xx 11   1W IFL     BOARD   2094-7xx 14   4W IFL   2,317   CHIP   8561-7xx 112   12W IFL     BOARD   2094-7xx 116   16W IFL   8,271   BOARD   8561-7xx 134   34W IFL	CORE	2084-3xx I1	1W IFL	443	z14		
BOARD   2004-3XX 14   4W IFL   1,713     CEC   2084-3XX 132   32W IFL   11,391     z9 EC   z9 EC/700   CEC   3906-7xx 133   33W IFL     CORE   2094-7xx 11   1W IFL   600   CORE   215   z15/700     CHIP   2094-7xx 14   4W IFL   2,317   CORE   8561-7xx 11   1W IFL     BOARD   2094-7xx 116   16W IFL   8,271   BOARD   8561-7xx 134   34W IFL	CHIP	2084-3xx 12	2W IFL	876		3906-7xx I1	
CEC   2084-3xx 132   32W IFL   I11,391     z9 EC   z9 EC/700   CEC   3906-7xx 1170   170W IFL     CORE   2094-7xx 11   1W IFL   600   CORE   8561-7xx 11   1W IFL     CHIP   2094-7xx 14   4W IFL   2,317   CHIP   8561-7xx 112   12W IFL     BOARD   2094-7xx 116   16W IFL   8,271   BOARD   8561-7xx 134   34W IFL	BOARD	2084-3xx 14	4W IFL	1,715			
z9 EC   z9 EC/700   CEC   3906-7xx 1170   170W IFL     CORE   2094-7xx 11   1W IFL   600   215   215/700     CHIP   2094-7xx 14   4W IFL   2,317   CORE   8561-7xx 11   1W IFL     BOARD   2094-7xx 116   16W IFL   8,271   BOARD   8561-7xx 134   34W IFL	CEC	2084-3xx 132	32W IFL	11,391			
CORE   2094-7xx I1   1W IFL   600   215   215/700     CHIP   2094-7xx I4   4W IFL   2,317   CORE   8561-7xx I1   1W IFL     BOARD   2094-7xx I16   16W IFL   8,271   CHIP   8561-7xx I12   12W IFL     BOARD   2094-7xx I16   16W IFL   8,271   BOARD   8561-7xx I34   34W IFL	z9 EC	z9 EC/700				CALL PROVIDE AND ADDRESS OF ADDRE	170W IFL
CHIP   2094-7xx I4   4W IFL   2,317   CORE   8561-7xx I1   1W IFL     BOARD   2094-7xx I16   16W IFL   8,271   CHIP   8561-7xx I12   12W IFL     BOARD   2094-7xx I16   16W IFL   8,271   BOARD   8561-7xx I34   34W IFL			1W IFL	600			
BOARD   2094-7xx I16   16W IFL   8,271   BOARD   8561-7xx I34   34W IFL				and the second			
BOARD 8301-7XX 134 34W IFE							
CEC 8561-7xx 190 190W IFL							
	GEC	2094-733 104	J4VV IFL	23,710	CEC	8561-7xx 1190	190W IFL

-

z10 EC/700

2097-7xx I1

2097-7xx 14

2097-7xx 112

1W IFL

4W IFL

12W IFI

z10 EC

CORE

CHIP

BOARD

Core: 278 > 443 > 600 > 990 > 1280 > 1650 > 1906 > 2020 > 2232 Chip: 278 > 876 > 2317 > 3701 > 4833 > 9097 > 13627 > 17783 > 23414 Server: 3804 > 11,391 > 23,716 > 43,426 > 68,410 > 103,699 > 154,904 > 195,496 > 240,718



## **IBM Z Chip Capacity Metrics**

		2097	z10	2817	z196	2827	zEC12	2964	z13	3906	z14	8561	z15
Release Date			1Q 2008		3Q 2010		3Q 2012		Q1 2015		3Q 2017		3Q 2019
SMT-1			n/a		n/a		n/a		1		1		1
Max-MIPS/Core	(MIPS)		990		1,280		1,650		1,906		2,020		2,232
Max-MIPS/Chip	(MIPS)		3,701		4,833		9,097		13,627		17,783		23,414
Max-MIPS/Drawer	(MIPS)		10,177		16,289		26,604		43,269		50,521		58,197
Max-MIPS/CEC	(MIPS)		43,426		68,410		103,699		154,904		195,496		240,718
SMT-2			n/a		n/a		n/a		2		2		2
SMT-2 Factor			n/a		n/a		n/a		20%		25%		27.50%
Max-MIPS/Core	(MIPS)		990		1,280		1,650		2,287		2,525		2,846
Max-MIPS/Chip	(MIPS)		3,701		4,833		9,097		16,352		22,229		29,853
Max-MIPS/Drawer	(MIPS)		10,177		16,289		26,604		51,923		63,151		74,201
Max-MIPS/CEC	(MIPS)		43,426		68,410		103,699		185,885		244,370		306,915
	9												
Max-MIPs/Core/GHz SMT1	(MIPS)		225		246		300		381		388		429
Max-MIPs/Core/GHz SMT2	(MIPS)		225		246		300		457		486		547

Look how much more work we can do!

Look how much more work we do per cycle!!!



# IBM Z Chip Technology Metrics

		2097	z10	2817	z196	2827	zEC12	2964	z13	3906	z14	8561	z15
Release Date			1Q 2008		3Q 2010		3Q 2012		Q1 2015		3Q 2017		3Q 2019
Max-GHz	(GHz)		4.4		5.2		5.5		5.0		5.2		5.2
Chip Transistors	(Billion)		1.00		1.40		2.75		3.99		6.10		9.10
Max Cores per Chip			4		4		6		8		10		12
Max Chips per MCM or Drawer			5		6		6		6		6		4
Max MCMs or Drawers per CEC			4		4		4		4		4		5
Max Chips per CEC			20		24		24		24	0	24		20
Max Core per CEC			80		96		144		192		240		240
Net Cache/Core	(M)		5.6		15.7		20.8		41.6		30.3		49.6
PU Chip Transistors	(B)		1.00		1.40		2.75		3.99		6.10		9.10
SC Chip Transistors	(B)		1.6		1.5		2.75		7.1		9.7		9.7
MAX KWs			27.5		30.1		27.6		29.8		29.8		28.1
Max-MIPS/CEC/KW	(MIPS)		1579		2273		3757		6238		8200		10922

#### Look how much more energy efficient we are!

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### Moore's Law

- https://en.wikipedia.org/wiki/Moore%27s\_law
- Moore's law is the observation that the number of transistors in a dense integrated circuit doubles about every two years. The observation is named after Gordon Moore, the co-founder of Fairchild Semiconductor and CEO of Intel, whose 1965 paper described a doubling every year in the number of components per integrated circuit<sup>[2]</sup> and projected this rate of growth would continue for at least another decade.<sup>[3]</sup> In 1975,<sup>[4]</sup> looking forward to the next decade,<sup>[5]</sup> he revised the forecast to doubling every two years.<sup>[6][7][8]</sup>

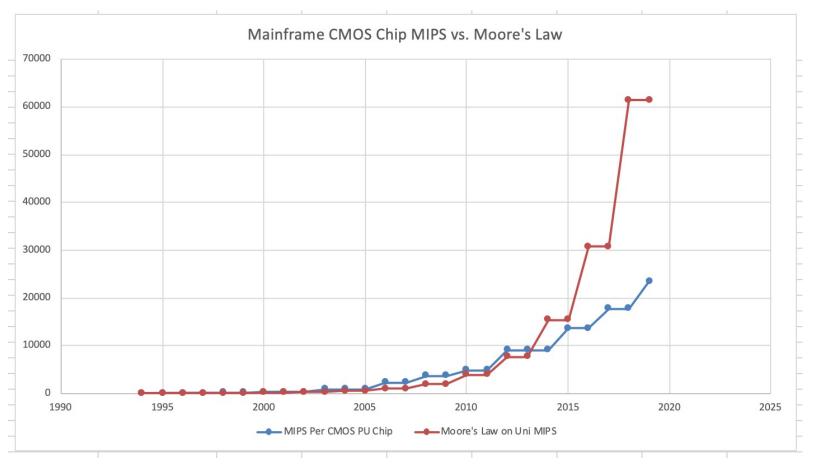
## MOORE ON MOORE'S LAW for MORE

- n April 2005, <u>Gordon Moore</u> stated in an interview that the projection cannot be sustained indefinitely: "It can't continue forever. The nature of exponentials is that you push them out and eventually disaster happens." He also noted that <u>transistors</u> eventually would reach the limits of miniaturization at <u>atomic</u> levels:
- In terms of size [of transistors] you can see that we're approaching the size of atoms which is a fundamental barrier, but it'll be two or three generations before we get that far—but that's as far out as we've ever been able to see. We have another 10 to 20 years before we reach a fundamental limit. By then they'll be able to make bigger chips and have transistor budgets in the billions.<sup>[100]</sup>

IBM. 🏵

### IBM Z Chip Chip MIPS vs. Moore's Law

Year	MIPS Per CMOS PU Chip	Moore's Law on Uni MIPS			
1994	15	15			
1995	22	15			
1996	45	30			
1997	63	30			
1998	117	60			
1999	176	60			
2000	235	120			
2001	235	120			
2002	278	240			
2003	876	240			
2004	876	480			
2005	876	480			
2006	2317	960			
2007	2317	960			
2008	3701	1920			
2009	3701	1920			
2010	4833	3840			
2011	4833	3840			
2012	9097	7680			
2013	9097	7680			
2014	9097	15360			
2015	13627	15360			
2016	13627	30720			
2017	17783	30720			
2018	17783	61440			
2019	23414	61440			





# IBM Z Chip Powered Platform MIPS vs. Moore's Law

ear	Single Image MIPS	Moore's Law on Single Image MIPS	300000		Mainframe	CMOS Server	MIPS vs. Moor	e's Law		
994	61	61	_							
995	186	61								
996	357	122	250000						<b>+</b> ••	
97	446	122	_						7	
98	1069	244	_							
999	1606	244								
000	3061	488	200000					•	4	
001	3061	488								
02	3804	976								
03	11391	976								
04	11391	1952	150000							
05	11391	1952								
06	23716	3904								
07	23716	3904								
08	43426	7808	100000							
09	43426	7808	-							
10	68410	15616	-				-			
11	68410	15616								
12	103699	31232	50000				2-0			
13	103699	31232	-				/ <u> </u>	4		
14	103699	62464	_							
15	154904	62464	0							
16	154904	124928	1990	1995	2000	2005	2010	2015	2020	2025
17	195496	124928	1330	1992	2000	2005	2010	2015	2020	2025
18	195496	249856	_			age MIPS — Mo	oore's Law on Single Im	age MIPS		
19	240718	249856						1070.00		



The End is Near

# THE END IS INEVITABLE



### IBM z15 Chip and LinuxONE III Holistic Performance

#### Scale Out

- Execute up to 1 trillion secure web transactions per day on a LinuxONE III server
- Scale-out to 2.4 million Docker containers in a LinuxONE III
- Consolidate 100 x86 running https to 1 LinuxONE III
- 20% TCO reduction over 5 years

#### **Competitive Results**

- Up to 2.3x more throughput running pgBench 9.6.1 read-only benchmark on PostgreSQL 11.1 vs. compared x86
- Up to 2.1x more throughput running YCSB 0.15 (write-heavy) benchmark on MongoDB 4.0.6 vs. compared x86
- Up to 2.8x more throughput running Cassandrastress benchmark on ScyllaDB 2.3.1 vs. compared x86 platform
- Up to 2.6x more throughput running DayTrader 7 benchmark on WAS Liberty vs. compared x86

#### **IBM Private Cloud and SSC**

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- Run 2.4x more AcmeAir containers per core deployed on ICP on LinuxONE III vs. compared x86
- Scale-up AcmeAir on SSC4ICP to 12 IFLs with 79% scaling efficiency on a LinuxONE III LPAR

#### Data Compression

- Compress up to 275 GB web data per second on a LinuxONE III server
- Up to 2.7x lower latency and up to 1.8x less CPU at 2.6x less network bandwidth running NGINX web server on LinuxONE III using Integrated zEDC to compress before encryption (up to 30x lower latency and up to 28x less CPU when compared to software compression)
- Up to 27x faster Db2 LUW database backup using 30x less CPU time using Integrated zEDC vs. compared x86 with software compression. (up to 20x faster using 23x less CPU time vs. LinuxONE Emperor II)
- Up to 6.5x faster MongoDB database dump using 5.5x less CPU time using Integrated zEDC vs. compared x86 with software compression. (up to 5.4x faster using 5.4x less CPU time vs. LinuxONE Emperor II)
- 3.2x faster MongoDB Dump on encrypted btrfs on LinuxONE III using Integrated Accelerator for zEDC compression versus compared x86 with software compression

#### **Instant Recovery**

 Start 100 KVM guests, in parallel, 2.1x faster on LinuxONE III LPAR versus using a compared x86

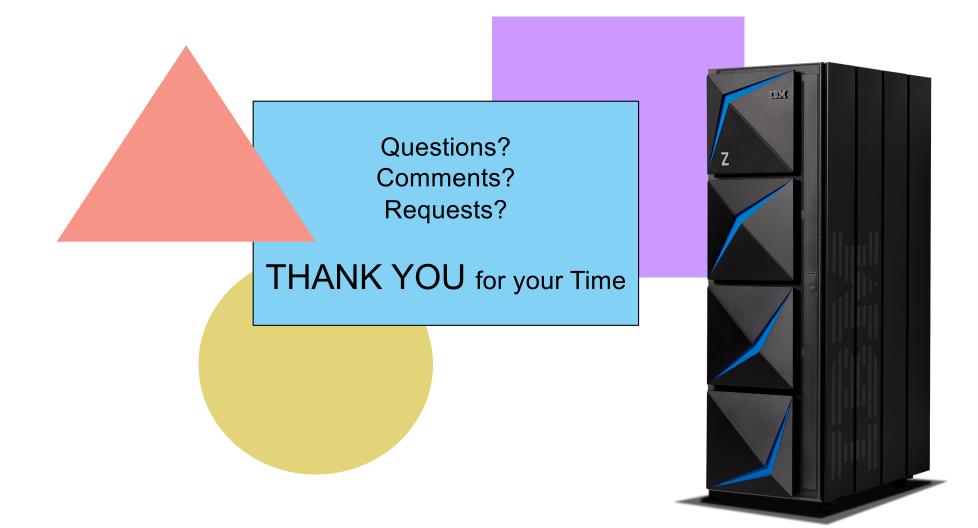


## The z15 Chip is Awesome – and so are LinuxONE III Servers!





### The Last Page



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